



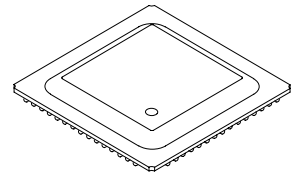
ATM Cell Processor

The ATM Cell Processor (MC92500) is a peripheral device composed of dedicated high performance Ingress and Egress Cell Processors combined with UTOPIA Compliant PHY and Switch Interface ports (see [Figure 1](#)).

MC92500 Features

- Full duplex operation at SONET STS-3c, SONET STS-1, DS3 PLCP, or any physical link running up to 155 Mbit/sec
- Implements ATM Layer functions for broadband ISDN according to ITU recommendations and ATM forum UNI specification
- Performs internal VPI and VCI address compression (with an option for external compression) for up to 64K VCs
- Supports up to 16 physical links using dedicated Ingress/Egress MultiPhy control signals
- Each physical link can be configured as either a UNI or NNI port
- Supports multicast, multipoint address translation
- Maintains both virtual connection and physical link counters on both Ingress and Egress cell flows for detailed billing and diagnostics
- Provides a flexible 32 bit external memory port for context management
- Automated AIS, RDI, CC and Loopback functions with Performance Monitoring Block Test on up to 64 Bidirectional connections
- Programmable 32 bit microprocessor interface supporting either big- or little-endian bus formats
- Per-connection leaky-bucket based UPC or NPC design with up to four buckets per connection allows any combination of CLP-aware peak, average, and burst-length policing with programmable tag/drop action per policer
- Implements separate rate controlled cell insertion and priority based cell extraction queues accessible from all cell flows
- Supports a programmable number of additional switch overhead parameters allowing adaptation to any switch routing header format

MC92500 ATM Cell Processor



ZQ SUFFIX
GTBGA
CASE 5203

Ordering Information

Device	Package
MC92500ZQ	256 GTBGA

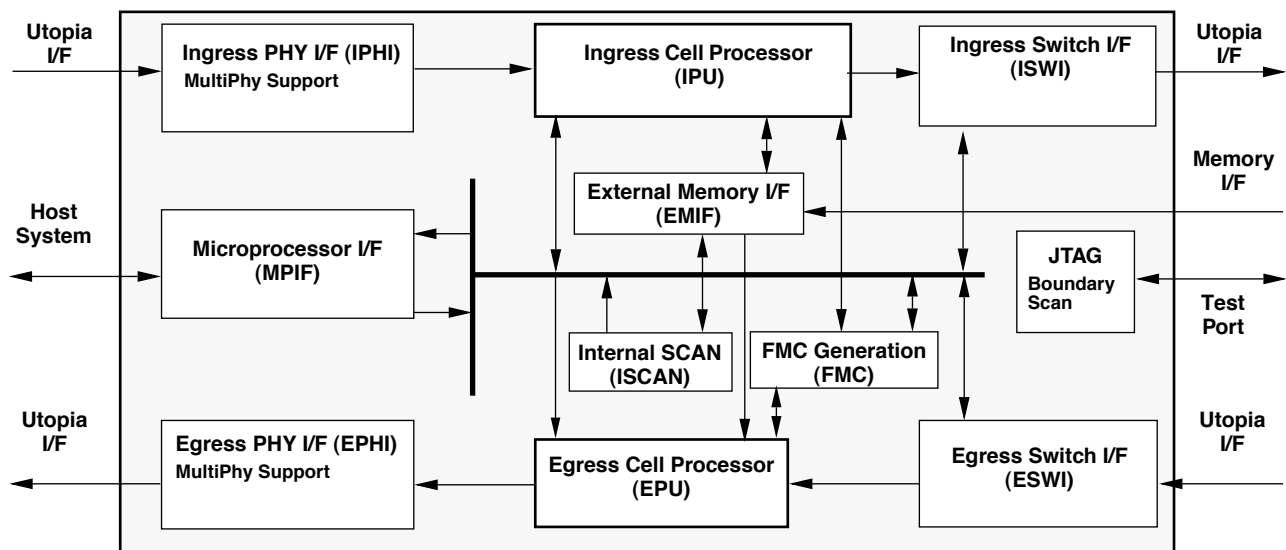


Figure 1. Representative Block Diagram

This document contains information on a new product. Specifications and information herein are subject to change without notice.

1. ATM NETWORK

1.1 ATM Network Description 3
 1.2 ATM Network Applications 4

2. FUNCTIONAL DESCRIPTION

2.1 System Functional Description 5
 2.2 MC92500 Functional Description 5
 2.2.1 Ingress Cell Flow 6
 2.2.2 Egress Cell Flow 6
 2.3 Other Functions 7
 2.4 MC92500 Block Diagram 7
 2.4.1 Ingress PHY Interface (IPHI) 8
 2.4.2 Ingress Cell Processing Unit (IPU) 8
 2.4.3 Ingress Switch Interface (ISWI) 8
 2.4.4 Egress Switch Interface (ESWI) 8
 2.4.5 Egress Cell Processing (EPU) 8
 2.4.6 Egress PHY Interface (EPHI) 9
 2.4.7 External Memory Interface (EMIF) 9
 2.4.8 Microprocessor Interface (MPIF) 9
 2.4.9 Internal Scan (ISCAN) 9
 2.4.10 Forward Monitoring Cell Generation(FMC) 9

3. REGISTERS DESCRIPTION

3.1 MC92500 Registers 9

4. EXTERNAL MEMORY DESCRIPTION

4.1 MC92500 External Memory 11
 4.1.1 Memory Partitioning 11

5. SIGNAL DESCRIPTION

5.1 Functional Signal Groups 13
 5.2 Ingress PHY Signals 13
 5.3 Egress PHY Signals 14
 5.3.1 Ingress Switch Interface Signals 14
 5.3.2 Egress Switch Interface Signals 15
 5.4 External Memory Signals 15
 5.4.1 Control Signals 16
 5.4.2 Microprocessor Signals (MP)..... 16
 5.4.3 Clock Signals 17
 5.4.4 JTAG Interface Test Signals 17

6. INGRESS DATA PATH OPERATION

6.1 Ingress Data Path 17

6.2 Interface to Physical Layer - Cell Assembly 18
 6.3 Address Compression 19
 6.4 Cell Counting 19
 6.5 Ingress Cell Insertion 20
 6.6 Switch Overhead Information 20
 6.7 Transfer to Switch 20

7. EGRESS DATA PATH OPERATION

7.1 Egress Data Path 20
 7.1.1 Transfer from Switch 21
 7.1.2 Multicast Identifier Translation 22
 7.1.3 Egress Cell Insertion 22
 7.1.4 Address Translation 22
 7.1.5 Cell Counting 22
 7.1.6 Transmission to Physical Layer 22

8. SYSTEM OPERATION

8.1 MC92500 Modes of Operation 23
 8.1.1 Setup Mode 23
 8.1.2 Operate Mode 23
 8.1.3 Reset 23
 8.2 Data Path Clock Configuration 23

9. ELECTRICAL CHARACTERISTICS

9.1 Electrical Specifications 24
 9.1.1 Clocks 24
 9.1.2 Microprocessor Interface Timing 25
 9.1.3 PHY Interface Timing 32
 9.1.4 Switch Interface Timing 33
 9.1.5 External Memory Interface Timing 34
 9.1.6 Write Cycle Timing 34
 9.1.7 Read Cycle Timing 35
 9.1.8 DC Electrical Characteristics 36

10. PACKAGE INFORMATION

10.1 Pin Assignment 38
 10.2 256 PBGA Case Outline 39

1. ATM NETWORK

1.1 ATM Network Description

A typical ATM network consists of user end stations that transmit and receive 53-byte data cells on virtual connections (see Figure 1). The virtual connections are implemented using physical links and switching systems that interconnect them. The specific combination of physical links that implements a virtual connection is chosen when the connection is established. On a given physical link, each connection is assigned a unique connection identifier. The connection identifier is placed in the header of each cell by the transmitting equipment and is used by the receiving equipment to route the cell to the next physical link on the connection path. All cells belonging to a specific virtual connection follow the identical path from the transmitting end station through the switching systems to the receiving end station.

Each switching system handles multiple physical links and transfers each arriving ATM cell from its source link to its destination link according to the pre-arranged

routing for the connection to which the cell belongs. The switching system consists of a switch fabric, which handles the actual routing of the cells, and a line card for each physical link (or group of links) to interface between the physical medium and the switch fabric. The line card recovers incoming cells from the arriving bit stream and converts outgoing cells into a bit stream for transmission.

ATM standards divide the tasks to be performed on each side of the switch fabric into PHY-layer and ATM-layer tasks. The PHY-layer tasks are dependent on the physical medium used to connect the switching systems, while the ATM-layer tasks operate at the cell level and are independent of the physical medium. Therefore, it is logical to implement the PHY-layer and ATM-layer functions on separate devices. In this case the line card appears as in Figure 2. There are one or more PHY-layer devices, an ATM-layer device, and clock recovery devices to clock the PHY devices in accordance with the signals arriving on the physical media.

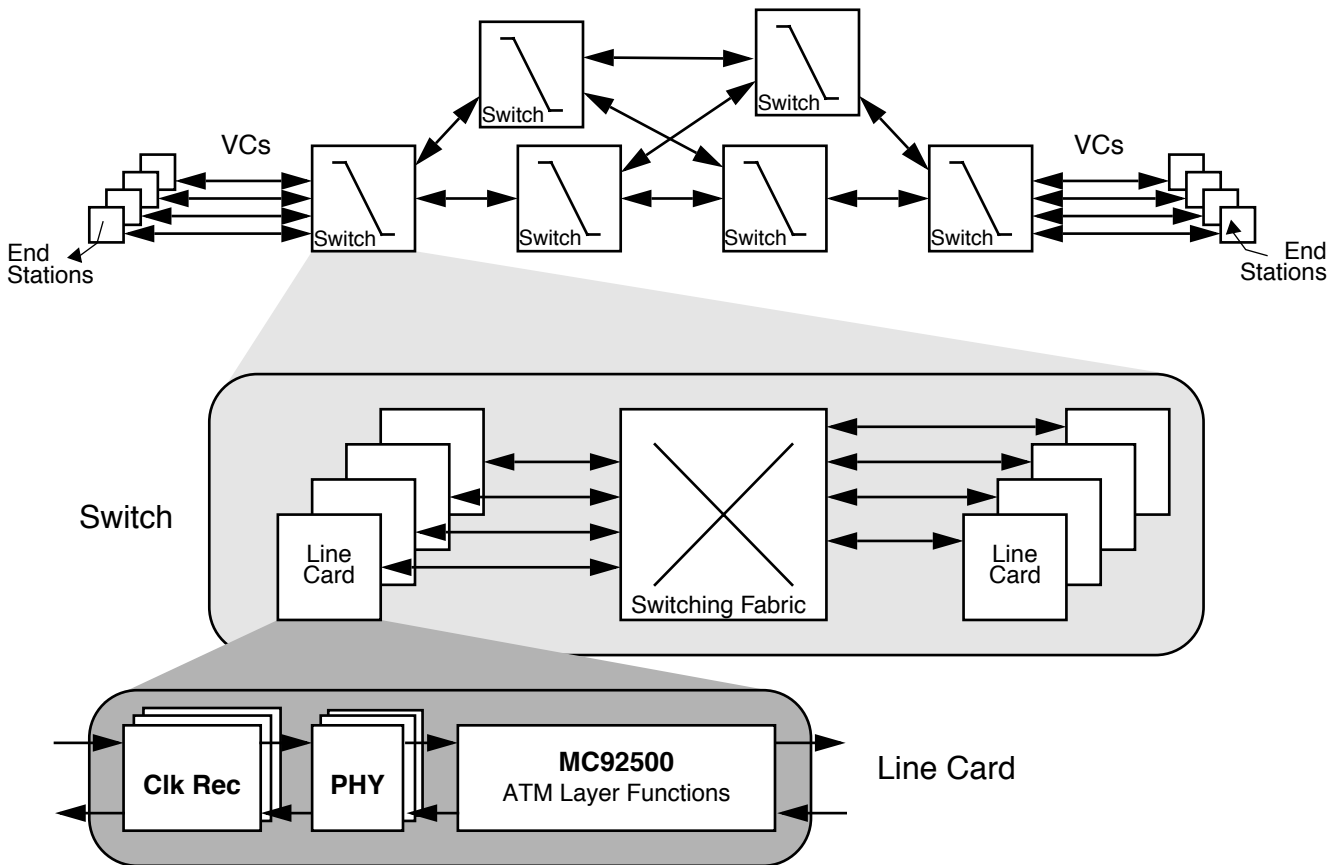


Figure 2. MC92500 in an ATM Network Application

1.2 ATM Network Applications

The MC92500, an Asynchronous Transfer Mode cell-processing device, is ideally suited for use in the interface between a PHY-layer device and an ATM switch fabric. The primary application of the MC92500 is ATM-layer cell processing and routing.

Figure 3 illustrates a typical ATM line card using the MC92500 device. The MC92500 uses an external memory for storing the ATM virtual connections of the cells it processes. In addition, the MC92500 offers an option to utilize an external address compression device accessed via the same external memory bus.

The microprocessor is used for configuration, control and status monitoring of the MC92500 and is responsible for initializing and maintaining the external memory. The MC92500 is the master of the external memory bus. At regular intervals the MC92500 allows the microprocessor to access the external memory for updating and maintenance.

System RAM can also be located on the line card. The MC92500 can support a DMA device to allow efficient data transfer to this RAM without processor intervention.

The physical interface (PHY-IF) implements the physical layer functions of the B-ISDN Protocol Reference Model. This includes the physical medium dependent functions required to transport ATM cells between the ATM user and the ATM switch (UNI) or between two ATM switches (NNI). The cells are transferred between the physical interface and the MC92500 using the UTOPIA standard.

The MC92500 implements B-ISDN UNI/NNI ATM-layer functions required to transfer cells to and from the switch over virtual connections. These functions include usage enforcement, address translation, and Operation and Maintenance (OAM) processing. The MC92500 provides context management for up to 64K Virtual Connections (VCs). The VCs can be either Virtual Path Connections (VPCs) or Virtual Channel Connections (VCCs). ATM cells belonging to a particular VCC on a logical link have the same unique Virtual Path Identifier/Virtual Channel Identifier, (VPI/VCI) value in the cell header. Similarly, cells belonging to a particular VPC on the same logical link share a unique VPI.

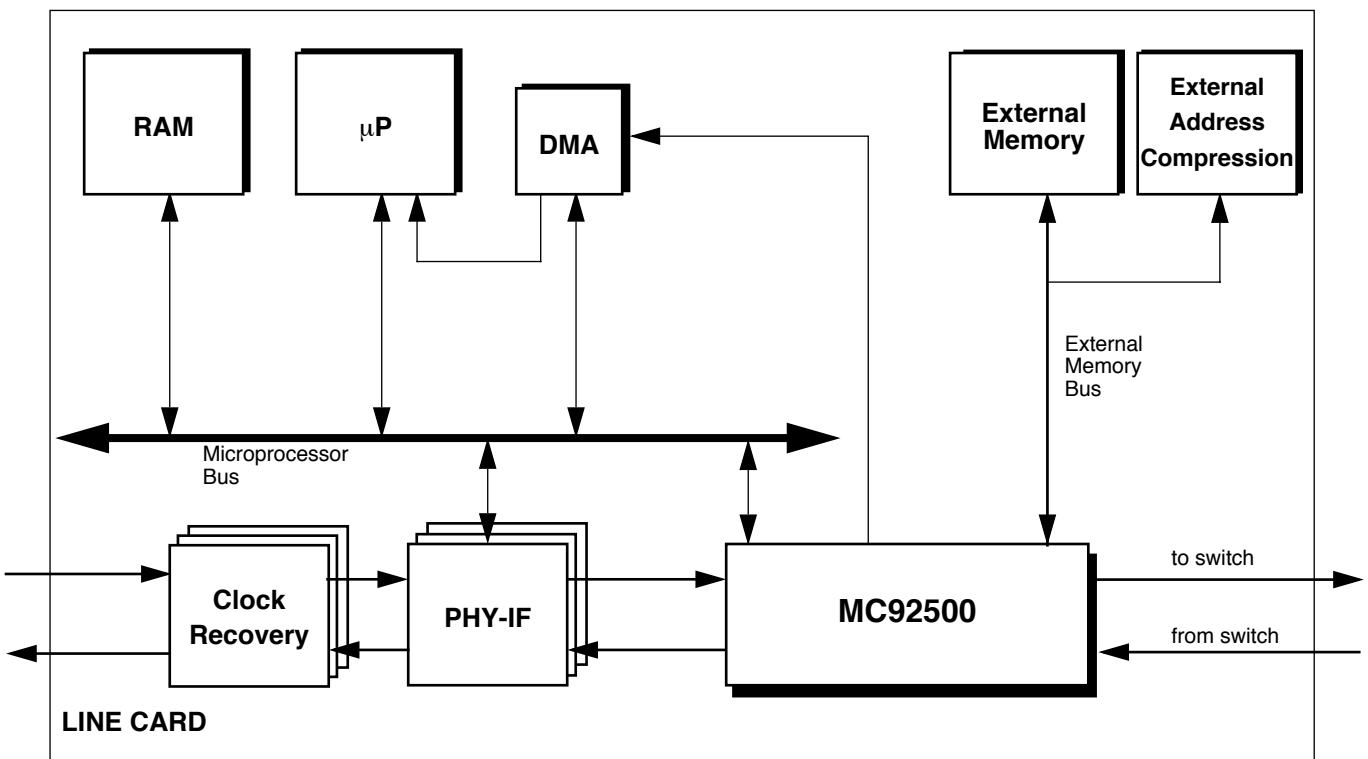


Figure 3. Typical MC92500 Line Card Application

2. FUNCTIONAL DESCRIPTION

2.1 System Functional Description

A serial transmission link operating at up to 155.52Mbit/sec (PHY) is coupled to the MC92500 via a byte-based interface. The transmission link timing is adapted to the MC92500 and switch timing by means of internal FIFO cell buffers. A common clock is used to supply both the PHY-IF and MC92500.

The host microprocessor initializes and provides real-time control of the data-flow chips (PHY-IF and MC92500) using slave accesses.

The MC92500 operates in conjunction with an external connection memory, which provides one context entry for each active connection. The entry consists of two types of context parameters: static and dynamic. The static parameters are loaded into the context memory when the VC is established, and are valid for the duration of that connection. Included in the static parameters are traffic descriptors, OAM flags and parameters used by the ATM switch. The dynamic context parameters, which include cell counters, UPC/NPC fields and OAM parameters, may be modified as cells belonging to that particular connection are processed by the MC92500. The microprocessor also accesses the external memory through the MC92500 from time to time to collect traffic statistics and to update the OAM parameters. During normal cell processing, the MC92500 has exclusive access to the external memory. The context entries for the cells being processed are read and the updated dynamic parameters are written back. The MC92500 is responsible for the coherency of the external memory during this time.

At user-programmable intervals the MC92500 provides the microprocessor with a “maintenance slot”, during which no cell processing is done, and relinquishes the external memory bus. The break in cell processing is made possible by the difference between the MC92500 cell-processing rate and the line rate.

The maintenance slot shall be used by the microprocessor for one or more of the following tasks:

- Connection setup and tear down
- Statistics collection
- Updating OAM parameters of active connection

The microprocessor is responsible for the coherency of the external memory at the end of each maintenance slot.

2.2 MC92500 Functional Description

MC92500 General Features

- Implements ATM Layer functions for Broadband ISDN according to CCITT recommendations and ATM forum user network interface specifications
- Provides a throughput capacity of up to 155 Mbit/sec in each direction
- Processes ATM cells from a SONET STS-3c, SONET STS-1, DS3 PLCP, or any other physical link running at up to 155 Mbit/sec
- Optionally supports up to 16 physical links
- Optionally configured as a User Network Interface (UNI) or Network Node Interface (NNI) on a per-link basis
- Operates in conjunction with an external memory (up to 16 MB) to provide context management for up to 64K Virtual Connections
- Provides explicit bank select signals to support up to four banks of external memory
- Provides per-connection cell counters with the ability to maintain multiple copies of the counter tables and dynamically switch between them
- Provides per-link cell counters in both directions
- Provides per-connection Usage Parameter Control (UPC) or Network Parameter Control (NPC) using a leaky bucket design with up to four buckets per connection
- Provides support for Operation and Maintenance (OAM) Continuity Check function for all connections
- Supports Virtual Path (VP) and Virtual Channel (VC) level Alarm Surveillance on all connections using an internal scan process to generate and insert OAM cells
- Supports OAM Fault Management Loopback test on all connections
- Supports bidirectional OAM Performance Monitoring on up to 64 connections
- Provides a slave microprocessor interface including a 32-bit data bus
- Provides byte-swapping on cell payloads to and from the microprocessor bus in order to support both big-endian and little-endian buses
- Supports cell insertion into the cell streams using direct access registers which may be written by the microprocessor or by a DMA device
- Supports copying cells from the cell streams using direct access registers which may be read by the microprocessor or by a DMA device
- Supports multicast operation

2.2.1 Ingress Cell Flow

In the Ingress direction, the MC92500 extracts cells from the FIFO in the PHY. Cell discrimination based on pre-defined header field values is performed to recognize unassigned and invalid cells. Cell rate decoupling is accomplished by discarding unassigned cells. Unassigned and invalid cell slots may be used to insert OAM and messaging cells into the Ingress cell flow. For VCCs, the 28-bit VPI/VCI address space (32-bit Link/VPI/VCI if multiple physical links are supported) needs to be compressed into a 16-bit Ingress Connection Identifier (ICI). The MC92500 provides a choice of two methods for performing VCC address compression to obtain the ICI: a table lookup based on reduced addressing and an external address compression option. For VPCs, the VPI field is used for a lookup into the VP Table to obtain the ICI. The ICI is a pointer used to access the context parameters for the current Ingress cell from the external context memory. Included in these parameters are cell counters, UPC/NPC traffic descriptor, OAM parameters and switch parameters.

The UPC/NPC mechanism entails counting the arriving cells and, using a flexible arrangement of traffic enforcement algorithms, admitting cells that do not violate the traffic characteristics established for that connection. Violating cells are tallied and may optionally be tagged or discarded (removed from the cell flow).

The OAM flags are used to control when and how OAM cells are processed and to determine if the current user cell belongs to a connection that has been selected for a performance monitoring test. If the Ingress cell belongs to such a connection, the OAM table in external memory contains the relevant parameters.

Subsequent to the context processing, the Ingress cells are transferred to the Ingress switch interface. Optionally, the associated switch context parameters may be added to the cell before the header or placed in the VPI/VCI fields of the header.

Ingress Features

The Ingress section (Ingress refers to cells being transferred from the physical interface to the switch):

- Interfaces to one or more physical interface chips via an 8-bit wide, parity-protected receive data bus using the UTOPIA standard
- Decouples PHY timing from switch timing using independent clocks and a FIFO in the physical interface
- Performs Ingress cell discrimination based on pre-assigned ATM cell header values

- Provides either a restricted address table lookup scheme for Ingress address compression or support for an external address compression mechanism
- Reads Virtual Connection related UPC/NPC, OAM and switch context parameters through a 32-bit wide interface to an external memory
- Provides per-connection usage count
- Provides per-connection option to copy cells to the microprocessor
- Provides per-connection UPC/NPC policing including detection/counting of violating cells
- Supports OAM continuity check, alarm surveillance and loopback test on all connections
- Provides OAM performance monitoring test capabilities for selected connections
- Supports insertion of cells into the ingress cell flow
- Optionally performs VPI/VCI translation
- Forwards the received ATM cells to the switch using a UTOPIA-style interface, optionally adding associated internal switch context parameters
- Delay of 3 - 5 cell times from the PHY to the switch

2.2.2 Egress Cell Flow

In the Egress direction, the MC92500 receives cells from the switch along with their associated parameters, if any. One of these parameters is the Egress Connection Identifier (ECI), which is used for direct lookup into the context table located in external memory to obtain the VPI/VCI, cell counters, and OAM flags. If multicast translation is enabled, the Multicast Identifier (MI) is received from the switch instead of the ECI, and the ECI is found in the multicast translation table. Cells are subject to processing as indicated by the OAM flags. If the Egress cell belongs to a connection that has been selected for a performance monitoring test, the OAM Table in external memory contains the relevant parameters.

The Egress cell header is generated by inserting the VPI/VCI-field obtained from the Address Translation Table in the (GFC)/VPI/VCI position and modifying the PTI-field if and when so indicated by the switch or in case of an OAM cell. The cell is then forwarded to the PHY I/F queue. Cell rate decoupling is performed in the Egress direction, i.e. unassigned cells are optionally generated if no cells are available from the switch.

Egress Features

The Egress section (Egress refers to cells being transferred from the switch to the physical interface):

- Receives ATM cells and associated switch context parameters (including congestion notification) from the switch using a UTOPIA-style interface
- Provides optional multicast identifier to connection identifier translation
- Reads Egress context parameters from external memory using direct lookup
- Provides per-connection usage count
- Provides per-connection option to copy cells to the microprocessor
- Supports OAM continuity check, alarm surveillance and loopback test on all connections
- Provides OAM performance monitoring test capabilities for selected connections
- Supports insertion of cells into the egress cell flow
- Performs VPI/VCI translation

- Transfers ATM cells to one or more physical interfaces via an 8-bit wide, parity-protected transmit data bus using the UTOPIA standard
- Decouples PHY timing from switch timing using independent clocks and a FIFO in the physical interface
- Delay of 3 - 5 cell times from the switch to the PHY

2.3 Other Functions

A general 32-bit slave system interface is provided for configuration, control, status monitoring, and insertion and extraction of cells. This interface provides for direct register access to the MC92500.

The MC92500 is equipped with a standard IEEE 1149.1 boundary scan test logic.

2.4 MC92500 Block Diagram

Figure 4 contains a block diagram of the MC92500. The individual blocks will be described in this section.

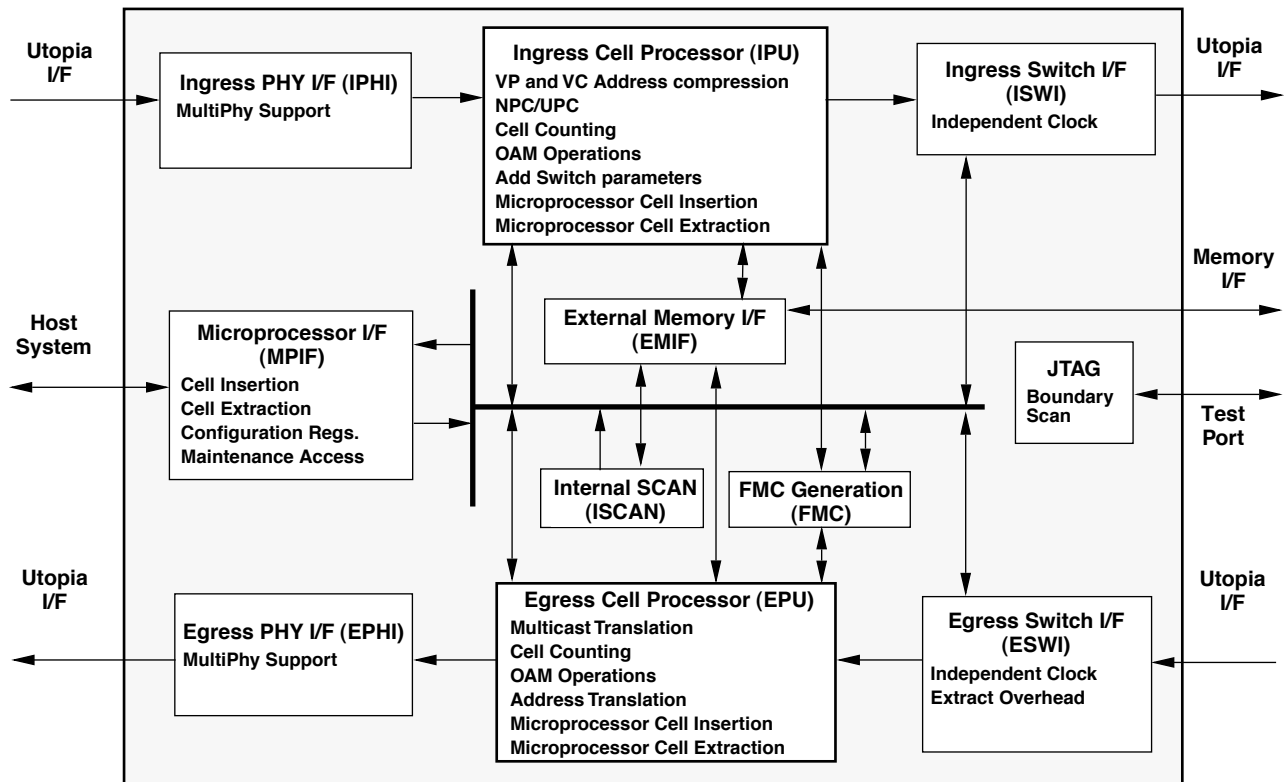


Figure 4. MC92500 Block Diagram

2.4.1 Ingress PHY Interface (IPHI)

The Ingress PHY Interface (IPHI) block receives cells on a byte basis from the ATM PHY layer using the UTOPIA standard interface. It assembles the cells and synchronizes their arrival to the MC92500 cell processing slots. Unassigned and invalid cells (Table 1 and Table 2) are removed to provide cell rate decoupling. Also, the MC92500 can process cells at a higher rate than the PHY provides them, thereby creating “holes” in the cell flow. These can be used for either cell insertion or for maintenance access (used by the microprocessor to maintain external memory).

2.4.2 Ingress Cell Processing Unit (IPU)

The Ingress Cell Processing Unit (IPU) operates at a rate of one cell per cell processing slot. The cell may have arrived from the IPHI block or may be inserted from the Microprocessor Interface or Internal Scan blocks. The Ingress OAM function may also insert PM Forward Monitoring cells into the Ingress cell flow. A cell may be inserted when an unused cell slot is available, subject to pacing by a simple leaky bucket algorithm.

The IPU performs address compression on cells that arrived from the IPHI block in order to associate the cell with Context Table records in External Memory. The address compression function detects inactive cells (cells with no corresponding records in the Context Table).

UPC/NPC is performed on a connection basis or optionally on arbitrary groups of connections. The UPC/NPC function may detect violating cells as dictated by the selected UPC/NPC algorithm. Violating cells will normally be tagged or discarded from the cell flow, but an option exists to perform the UPC/NPC algorithm for statistical purposes only without modifying or removing the cells.

OAM processing is performed where appropriate. The Ingress OAM function records OAM alarm cells: Alarm Indication Signal/Remote Defect Indicator (AIS/RDI). OAM processing for user cells involved in a performance monitoring block test involves computing the Bit-Interleaved Parity (BIP) and updating the Total User Cells (TUC) count. For OAM cells the processing may include overwriting the values of specific fields and checking or generating the CRC-10 field.

Switch-specific overhead information is read from the context entry and added to the cell before it is sent on to the switch interface block. Address translation may optionally be performed at this point.

The IPU will remove from the cell flow any OAM cell that has reached its endpoint. Also, certain cells may be copied to the MPIF for transfer to the microprocessor.

2.4.3 Ingress Switch Interface (ISWI)

The ISWI block contains a cell FIFO. Cells are received from the IPU. When a full cell has been transferred, the overhead information needed by the switch (as programmed by the user) is extracted from the internal data structure along with the ATM header and payload of the cell. This information is transferred to the switch at the rate of one byte per clock cycle.

2.4.4 Egress Switch Interface (ESWI)

The ESWI block contains a cell FIFO. Data is received from the switch at the rate of one byte per clock cycle. The data structure received from the switch includes overhead routing information in addition to the ATM cell. When a full cell has been transferred, it is transformed into an internal data structure and presented to the EPU for processing.

2.4.5 Egress Cell Processing (EPU)

The Egress Cell Processing Unit (EPU) operates at the rate of one cell per cell processing slot. The cell may arrive from the Egress Switch Interface Block or may be inserted from the Microprocessor Interface or Internal Scan Blocks. The Egress OAM function may also insert PM Forward Monitoring cells into the Egress cell flow. The cell insertion is paced by a simple leaky bucket algorithm.

The first stage of the Egress cell processing is performing multicast translation, if needed. Then the EPU performs OAM processing where appropriate. The Egress OAM function records OAM Alarm cells. OAM processing for user cells involved in a Performance Monitoring block test is limited to computing the bit-interleaved parity and updating the Total User Cells count. For OAM cells the processing may include over-writing the values of specific fields and checking or generating the CRC-10 field.

Address translation is performed to replace the address fields of the ATM cell header with the address of the outgoing link. The EPU will remove from the cell flow any OAM cell that has reached its endpoint. Also, certain cells may be copied to the MPIF for transfer to the microprocessor.

2.4.6 Egress PHY Interface (EPHI)

The Egress PHY Interface (EPHI) block takes the processed cells from the EPU, disassembles them into bytes and transfers them to the physical layer using the UTOPIA standard interface. Unassigned cells may be inserted to provide cell rate decoupling.

2.4.7 External Memory Interface (EMIF)

The External Memory Interface (EMIF) block performs address generation for the MC92500 accesses to the external memory. It provides 32-bit data and 22-bit address lines along with standard memory control signals.

2.4.8 Microprocessor Interface (MPIF)

The Microprocessor Interface (MPIF) block provides for configuration of the MC92500, the transfer of cells between the microprocessor and the MC92500, and the maintenance of external memory. A generic 68xxx - compatible 32-bit slave interface is provided for easy connection to a variety of microprocessor buses. Output signals are provided that can serve as request signals for up to three DMA devices to improve system performance.

A cell extraction queue is used to store cells that are directed to the processor. Cells in this queue are transferred first to an internal cell buffer. Then they may be read by the processor.

Cells to be inserted in the Ingress or Egress flows are transferred from the processor memory to an internal insertion queue.

2.4.9 Internal Scan (ISCAN)

The Internal Scan (ISCAN) block scans the external memory for connections on which AIS, RDI, or Continuity Check (CC) OAM cells must be inserted. When such a connection is found, the cells are generated and added to the insertion queue for the cell flow in the appropriate direction.

2.4.10 Forward Monitoring Cell Generation (FMC)

The Forward Monitoring Cell (FMC) Generation block keeps track of the connections on which FMCs are pending during the course of a Performance Monitoring block test and maintains a priority among them. When a hole in the cell flow is available, this block requests the insertion of an FMC on the highest-priority connection.

3. REGISTERS DESCRIPTION

3.1 MC92500 Registers

The MC92500 registers are divided into several groups. The register groups are:

Status Reporting Registers - these registers report on the MC92500 status, and generally may be read and written by the processor in either of the MC92500 modes of operation (Setup Mode or Operate Mode).

Control Registers - these registers control the MC92500 operation, and may be read and written by the processor in either of the MC92500 modes of operation (Setup Mode or Operate Mode).

Configuration Registers - these registers are used to define the MC92500 configuration, and may be read by the processor in either of the MC92500 modes of operation (Setup Mode or Operate Mode). These registers may be written by the processor only in Setup Mode of operation.

Cell Insertion Registers - these registers are used for cell insertion into the MC92500 cell flow, and may be written by the processor when the MC92500 is in Operate Mode. In order to improve performance, the MC92500 Cell Insertion Registers receive special treatment and may be accessed without wait states.

Cell Extraction Registers - these registers are used for copying cells from the MC92500 cell flows, and may be read by the processor when the MC92500 is in Operate Mode. In order to improve performance, the MC92500 Cell Extraction Registers receive special treatment and may be accessed without wait states.

Pseudo Registers - these registers are used to perform certain operations on the MC92500, and may be written by the processor in either of the MC92500 modes of operation (Setup Mode or Operate Mode).

External Address Compression Device - this memory space may be used by the processor to access the external address compression device. The External Address Compression Device may be accessed when the MC92500 is in Setup Mode or during maintenance slots.

External Memory - this memory space may be used by the processor to access the External Memory. If the “De-

structive” memory space is used, the MC92500 will automatically provide a write-back of zeros to each External Memory location that is read. The External Memory may be accessed when the MC92500 is in Setup Mode or during maintenance slots.

Figure 5 presents the MC92500 memory space addressable by the microprocessor using the MADD bus.

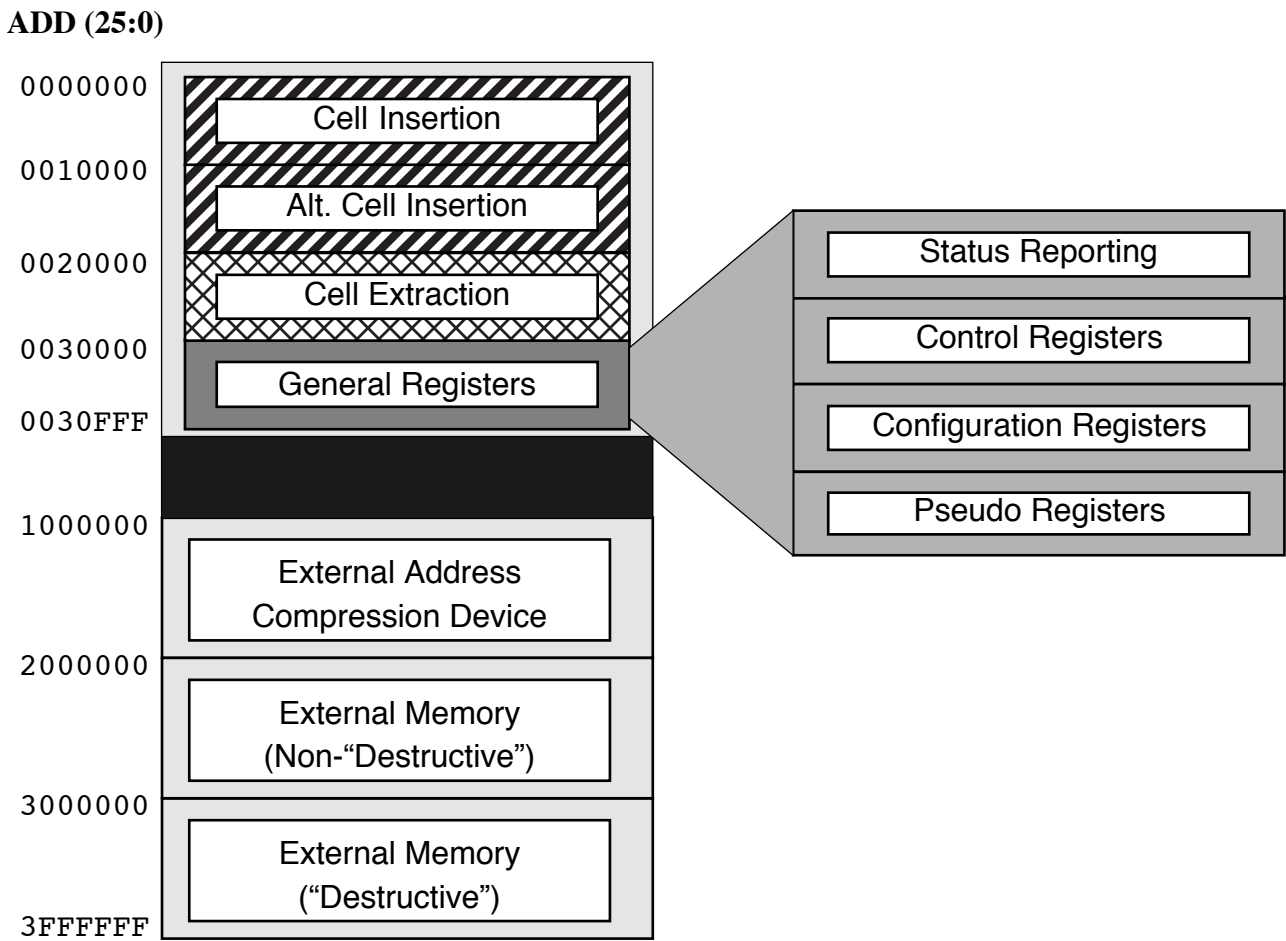


Figure 5. MC92500 Processor Memory Map

4. EXTERNAL MEMORY DESCRIPTION

4.1 MC92500 External Memory

The MC92500 uses external memory to store the database (context information) relating to the processing of cells on a per-connection basis. The MC92500 can access External Memory with 16- or 32-bit data.

4.1.1 Memory Partitioning

The External memory is partitioned into several tables: (see [Figure 6](#))

- Ingress Billing Counters - consists of a record for each active connection. The record contains the cell counters that are used by the connection during the normal Ingress cell flow. This table is dynamic and updated by the MC92500. The microprocessor is responsible for collecting the contents of the counters on a regular basis.
- Egress Billing Counters - consists of a record for each active connection. The record contains the counters that are used by the connection during the normal Egress cell flow. This table is dynamic and updated by the MC92500. The microprocessor is responsible for collecting the contents of the counters on a regular basis.
- Flags Table - consists of a record for each active connection. The record contains OAM flags that are used by all the connections during the normal cell flow. This table is dynamic and updated by the MC92500. The microprocessor is responsible for checking the flags on a regular basis
- Context Parameters Table - consists of a record for each active connection. The record contains connection-specific information for processing and routing the cells belonging to the connection.
- Ingress Policing Counters - consists of a record for each active connection. The record contains the counters that are used to record the results of the UPC/NPC policing. This table is dynamic and updated by the MC92500. The microprocessor is responsible for collecting the contents of the counters on a regular basis.
- VC Table - contains a list of all the Ingress Connection Identifiers (ICIs) that have been defined by the microprocessor as active Virtual Channel Connections. This table exists only if the Table Lookup method of Address Compression is used with VC Table Lookup enabled.
- Multicast Translation Table - contains the Egress Connection Identifiers (ECIs) associated with the multicast identifiers.
- OAM Table - contains the additional information required to run OAM Performance Monitoring.
- VP Table(s) - each record contains an Ingress Connection Identifier (ICI) that has been defined by the microprocessor as an active connection. The size and location of the VP Table(s) are determined by the Link Register. If multiple links are supported, each Link Register defines a separate VP Table. The multiple VP Tables are not required to be contiguous.
- Dump Vector Table - contains the dump vectors describing the recent history of the cell processing. This table is generally only used for debugging purposes.
- Egress Link Counters - consists of a record for each link. The record contains the cell counters that are used by the link during the normal Egress cell flow. This table is dynamic and updated by the MC92500. The microprocessor is responsible for collecting the contents of the counters on a regular basis.
- Ingress Link Counters - consists of a record for each link. The record contains the cell counters that are used by the link during the normal Ingress cell flow. This table is dynamic and updated by the MC92500. The microprocessor is responsible for collecting the contents of the counters on a regular basis.
- Virtual Bucket Table - each record in this table contains the information for the UPC/NPC enforcement. This is not a physical table, but a virtual one. Since the Parameters Table contains a full address for the location of the Bucket record of each connection, there is no need to put all the Bucket records in consecutive physical locations. Although the user can distribute the records in any manner.

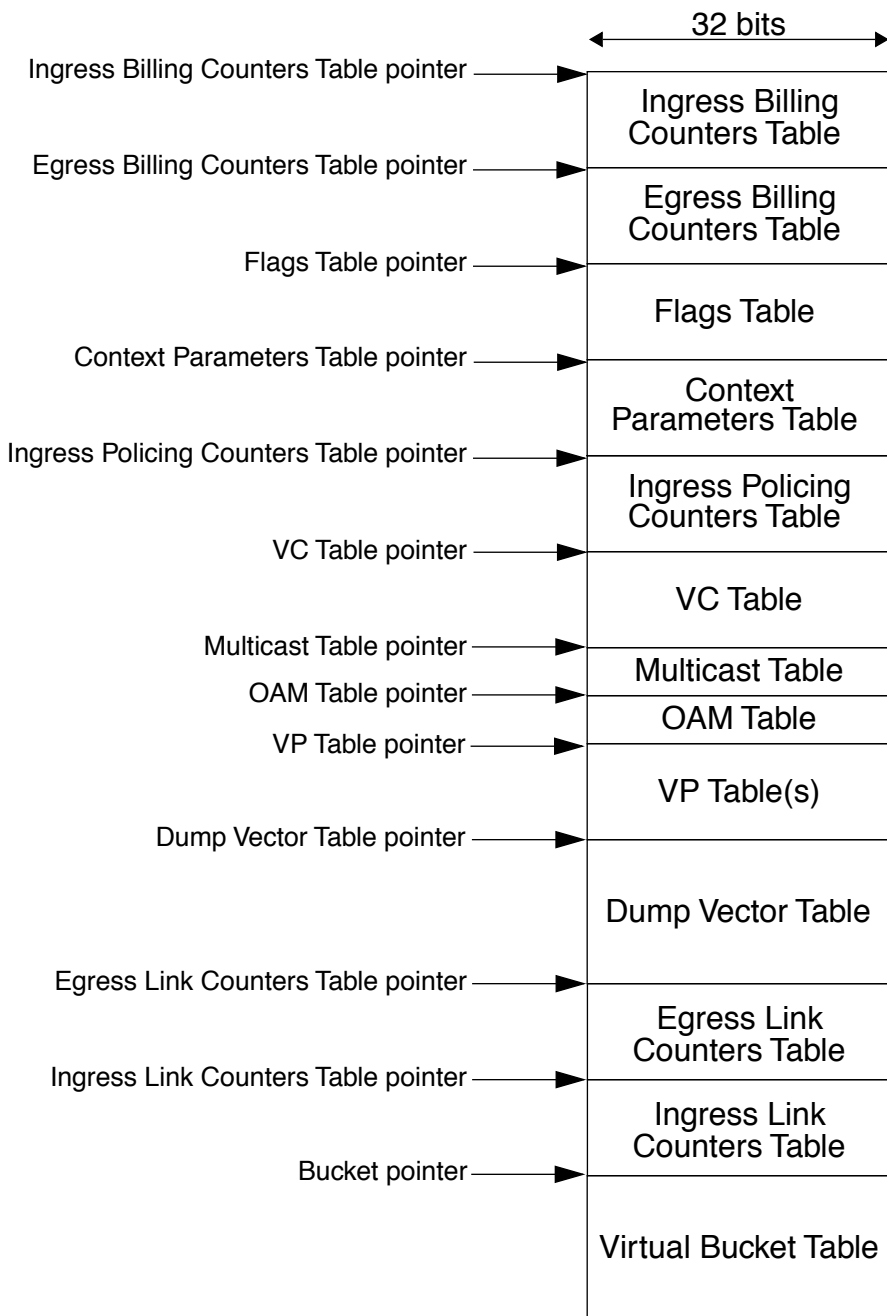


Figure 6. External Memory Partitioning

5. SIGNAL DESCRIPTION

5.1 Functional Signal Groups

This section contains brief descriptions of the input and output signals in their functional groups, as shown in Figure 7. Each signal is explained briefly.

5.2 Ingress PHY Signals

The following signals relate to the PHY interface that is connected to the PHY chip(s) using the UTOPIA standard. All of the input signals are sampled at the rising edge of ACLK, and all of the output signals are updated at the rising edge of ACLK.

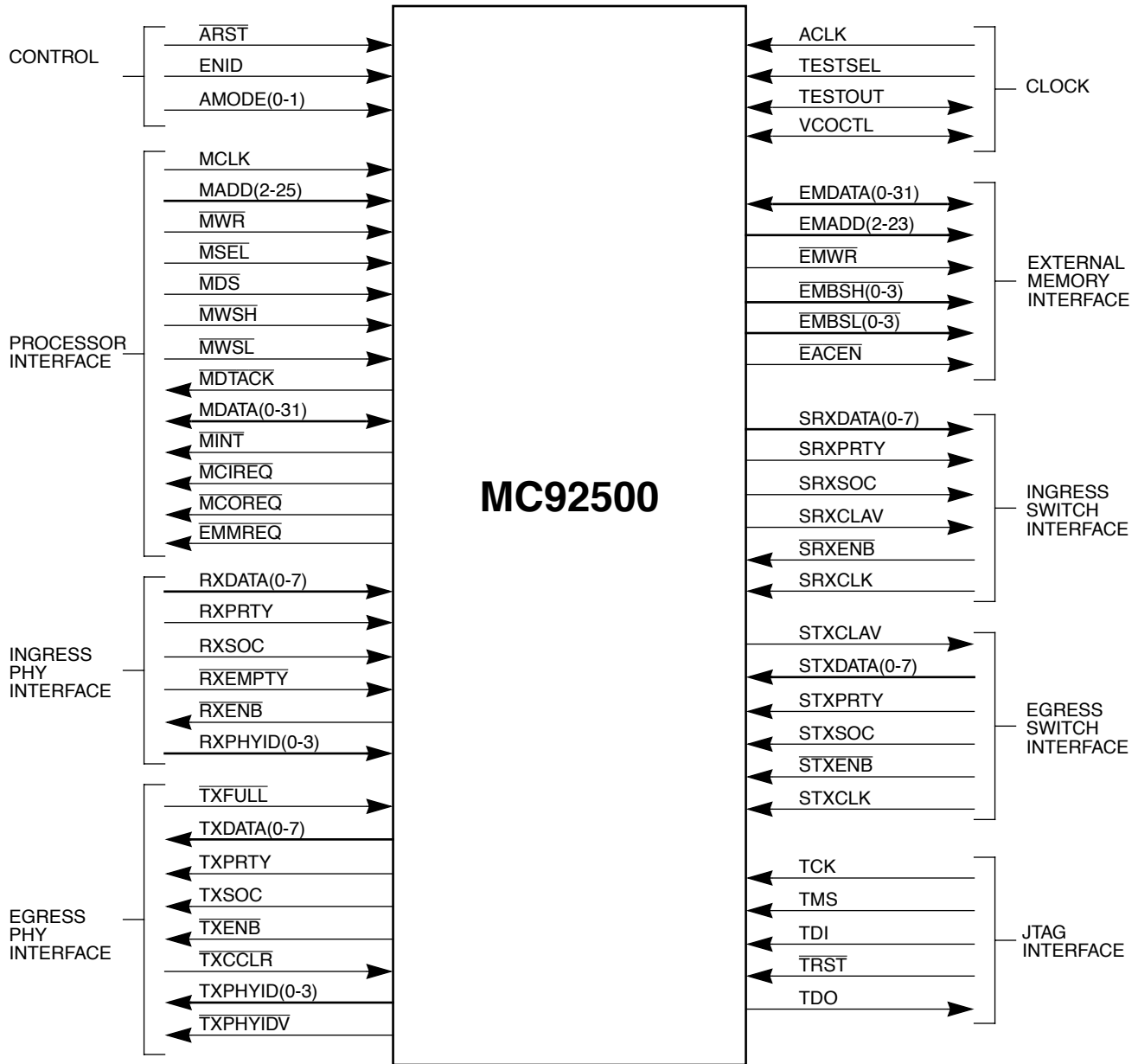


Figure 7. Functional Signal Groups

Receive Data Bus (RXDATA0 - RXDATA7)

This input data bus receives octets from the PHY chip. When \overline{RXENB} is active, RXDATA is sampled into the MC92500.

Receive Data Bus Parity (RXPRTY)

This input is the odd parity over RXDATA. This input is ignored if \overline{RXENB} was not active or the parity check is disabled.

Receive Start Of Cell (RXSOC)

This input, when high, indicates that the current RXDATA is the first byte of a cell. This input is sampled when \overline{RXENB} is active.

Receive PHY Empty (RXEMPTY)

This input, when low, indicates that currently the PHY chip has no available data.

Receive Enable (\overline{RXENB})

This output, when low, indicates that the MC92500 is ready to receive data.

Receive PHY ID (RXPHYID0 - RXPHYID3)

This input bus indicates the ID number of the PHY device currently transferring data to the MC92500. If only a single PHY device is supported, this bus should be tied low. This bus is sampled along with the first octet of each cell.

5.3 Egress PHY Signals

The following signals relate to the PHY interface that is connected to the PHY chip(s) using the UTOPIA standard. All of the input signals are sampled at the rising edge of ACLK, and all of the output signals are updated at the rising edge of ACLK.

Transmit Data Bus (TXDATA0-TXDATA7)

This output data bus transmits octets to the PHY chip. When \overline{TXENB} is active, TXDATA contains a valid octet for the PHY.

Transmit Data Bus Parity (TXPRTY)

This output signal is the odd parity over TXDATA. When \overline{TXENB} is active, TXPRTY is a valid parity bit for the PHY.

Transmit Enable (\overline{TXENB})

This output signal, when low, indicates that TXDATA, TXPRTY, and TXSOC are valid data for the PHY.

Transmit Start Of Cell (TXSOC)

This output signal indicates, when high, that the current data on TXDATA is the first byte of a cell. TXSOC is valid when \overline{TXENB} is asserted.

Transmit PHY Full (\overline{TXFULL})

This input signal indicates, when low, that the PHY device is full.

Transmit Cell Clear (\overline{TXCCLR})

This input signal indicates, when low, that the current cell should be cleared from the Egress PHY interface.

Transmit PHY ID (TXPHYID0 - TXPHYID3)

This output bus indicates the ID number of the PHY device to which either the current cell or the next cell is directed.

Transmit Next PHY ID Valid ($\overline{TXPHYIDV}$)

This output signal, when low, indicates that TXPHYID (when configured as the next cell's ID) is valid. If TXPHYID is configured to refer to the current cell, $\overline{TXPHYIDV}$ is not used.

5.3.1 Ingress Switch Interface Signals

The following signals relate to the Ingress switch interface. All of the input signals are sampled at the rising edge of SRXCLK, and all of the output signals are updated at the rising edge of SRXCLK.

Receive Clock (SRXCLK)

This input signal is used to clock the ingress switch interface signals.

Receive DATA BUS (SRXDATA0-SRXDATA7)

This 3-state output data bus transmits bytes to the switch. When \overline{SRXENB} is active, SRXDATA contains valid data for the switch. This bus is updated on the rising edge of SRXCLK.

Receive Data Bus Parity (SRXPRTY)

This 3-state output is the parity protection of SRXDATA transmitted to the switch. It is output on the rising edge of SRXCLK.

Receive Start Of Cell (SRXSOC)

This 3-state output, when high, indicates that the current data on SRXDATA is the first byte of a cell structure (including the overhead bytes). It is output on the rising edge of SRXCLK.

Receive Switch Cell Available (SRXCLAV)

This output, when asserted, indicates that the MC92500 has a cell ready to transfer to the switch. When negated, it indicates that currently there is no data available for the switch. It is output on the rising edge of SRXCLK.

Receive Enable ($\overline{\text{SRXENB}}$)

This input, when low, enables new values on SRXDATA, SRXPRTY and SRXSOC. This input is sampled on the rising edge of SRXCLK.

5.3.2 Egress Switch Interface Signals

The following signals relate to the Egress switch interface. All of the input signals are sampled at the rising edge of STXCLK, and all of the output signals are updated at the rising edge of STXCLK.

Transmit Clock (STXCLK)

This input signal is used to clock the egress switch interface signals.

Transmit Data Bus (STXDATA0 - STXDATA7)

This input data bus receives bytes from the switch. When $\overline{\text{STXENB}}$ is asserted, STXDATA is sampled into the MC92500 on the rising edge of STXCLK.

Transmit Data Bus Parity(STXPRTY)

This input is the parity over STXDATA. This input is ignored if $\overline{\text{STXENB}}$ is negated or the parity check is disabled. It is sampled on the rising edge of STXCLK.

Transmit Start Of Cell (STXSOC)

This input indicates, when high, that the current data is the first byte of a cell structure (including the overhead bytes). This input is sampled on the rising edge of STXCLK when $\overline{\text{STXENB}}$ is asserted.

Transmit Enable ($\overline{\text{STXENB}}$)

This input, when low, enables STXDATA, STXPRTY, and STXSOC. It is sampled on the rising edge of STXCLK.

Transmit Cell Available (STXCLAV)

This output, when asserted, indicates that the MC92500 is prepared to receive a complete cell. It is output on the rising edge of STXCLK.

5.4 External Memory Signals

The following signals relate to the External memory interface.

External Memory Data Bus (EMDATA0-EMDATA31)

This three-state bidirectional bus provides the data path between the MC92500 and the External Memory.

External Memory Address Bus (EMADD2-EMADD23)

This output bus provides the general address bus which is used by the MC92500 in its accesses to the External Memory.

External Memory Write ($\overline{\text{EMWR}}$)

This output signal indicates that the current cycle to the External Memory is a write cycle. This signal is active low and is asserted within the cycle.

External Memory Bank Select High ($\overline{\text{EMBSH0}}$ - $\overline{\text{EMBSH3}}$)

These output signals are used to select the high word of the appropriate memory bank. One or more of these signals is asserted for each External Memory access according to the value of EMADD. During a maintenance write access from the microprocessor, the value detected on $\overline{\text{MWSH}}$ is driven on the appropriate $\overline{\text{EMBSH}}$ signal. These signals are active low.

External Memory Bank Select Low ($\overline{\text{EMBSL0}}$ - $\overline{\text{EMBSL3}}$)

These output signals are used to select the low word of the appropriate memory bank. One or more of these signals is asserted for each External Memory access according to the value of EMADD. During a maintenance write access from the microprocessor, the value detected on $\overline{\text{MWSL}}$ is driven on the appropriate $\overline{\text{EMBSL}}$ signal. These signals are active low.

External Address Compression Enable ($\overline{\text{EACEN}}$)

This output signal is asserted when data is being written to or read from an external address compression device using the External Memory Data Bus. This signal is active low.

5.4.1 Control Signals

These signals are used to control the MC92500.

ATMC Power-Up Reset ($\overline{\text{ARST}}$)

This input signal is used for power-up reset of the entire chip. It must be asserted for at least the time required by the PLL to lock.

Enable IDD (ENID)

This input is a dedicated test signal which must be grounded during normal system operation.

ATMC Mode (AMODE0-AMODE1)

These inputs are dedicated test signals which must be grounded during normal system operation.

5.4.2 Microprocessor Signals (MP)

The following signals relate to the microprocessor interface.

MP Clock (MCLK)

This input signal is used as the Microprocessor clock inside the MC92500. This signal drives the microprocessor interface logic in the MC92500. The duty cycle should be in the range of 40-60%.

MP Data Bus (MDATA0-MDATA31)

This 3-state bidirectional bus provides the general data path between the MC92500 and the microprocessor.

MP Address Bus (MADD2-MADD25)

This input bus contains the address which is used by the microprocessor to define the register being accessed. This bus is used by the MC92500 at the assertion of $\overline{\text{MSEL}}$ and sampled on the falling edge of MCLK.

MP Select ($\overline{\text{MSEL}}$)

This input signal is used to determine that the current access to the MC92500 is valid. This signal is active low and sampled by the MC92500 on the falling edge of MCLK.

MP Data Select ($\overline{\text{MDS}}$)

This input signal is used to indicate when the data on MDATA is valid during a write access to the MC92500. This signal is active low and sampled by the MC92500 on the falling edge of MCLK.

MP Write ($\overline{\text{MWR}}$)

This input signal is used to determine whether the MP is reading from the MC92500 or writing to it. This signal is active low and sampled by the MC92500 on the falling edge of MCLK. The MC92500 will drive MDATA when $\overline{\text{MSEL}} = 0$ and $\overline{\text{MWR}} = 1$.

MP Word Select High ($\overline{\text{MWSH}}$)

This input signal indicates that the high word is being accessed. During a maintenance access, the value detected on $\overline{\text{MWSH}}$ is driven on the appropriate $\overline{\text{EMBSH}}$ signal. This signal is active low and sampled by the MC92500 on the falling edge of MCLK.

MP Word Select Low ($\overline{\text{MWSL}}$)

This input signal indicates that the low word is being accessed. During a maintenance write access, the value detected on $\overline{\text{MWSL}}$ is driven on the appropriate $\overline{\text{EMBSL}}$ signal. This signal is active low and sampled by the MC92500 on the falling edge of MCLK.

Note: All Cell Extraction Register, Cell Insertion Register, and General Register accesses are long-word (32-bit) accesses, so both $\overline{\text{MWSH}}$ and $\overline{\text{MWSL}}$ should be asserted low for these accesses.

MP Data Acknowledge ($\overline{\text{MDTACK}}$)

This three-state output signal is used to indicate when the data on MDATA is valid during a read access from the MC92500 or when the data has been sampled during a write access to the MC92500. At the end of each access, this signal is actively pulled up and then 3-stated (Hi -Z). The user may program the MC92500 not to drive $\overline{\text{MDTACK}}$ during certain types of accesses. This signal is active low and is output asynchronously to MCLK.

MP Interrupt ($\overline{\text{MINT}}$)

This output signal is used to notify the microprocessor of the occurrence of interrupting events. This signal is asserted on the rising edge of ACLK (asynchronous with respect to MCLK).

MP Cell In Request ($\overline{\text{MCIREQ}}$)

This output signal may be used by an external DMA device as a control line indicating when to start a new cell insertion cycle into the MC92500. This signal is asserted whenever the Cell Insertion Register array is available to be written. This signal is active low and is output on the falling edge of MCLK.

MP Cell Out Request ($\overline{\text{MCOREQ}}$)

This output signal may be used by an external DMA device as a control line indicating when to start a new cell extraction cycle from the MC92500. This output is asserted whenever the Cell Extraction Register array is available to be read. This signal is active low and is output on the falling edge of MCLK.

External Memory Maintenance Request ($\overline{\text{EMMREQ}}$)

This output signal is asserted a programmable number of clock cycles before the start of an external memory maintenance cycle. It is negated after a programmable number of maintenance accesses have been performed. This signal is active low and is output on the falling edge of MCLK.

5.4.3 Clock Signals

The following signals are connected to the analog PLL which is used in the MC92500 ACLK.

ATMC Master Clock (ACLK)

This input signal is used by the PLL to generate the internal master clock of MC92500. The duty cycle should be in the range of 40-60%.

TESTSEL

This input is a dedicated test signal which must be grounded during normal system operation.

TESTOUT

This 3-state output is a dedicated test signal which must be grounded during normal system operation.

VCOCTL

This is a dedicated test signal which must be connected to the analog ground (AVSS) during normal system operation.

5.4.4 JTAG Interface Test Signals

Test Clock (TCK)

This input pin is the JTAG clock. The TDO, TDI, and TMS pins are synchronized by this pin.

Test Mode Select (TMS)

This input pin is sampled on the rising edge of TCK. TMS is responsible for the state change in the test access port state machine.

Test Data Input (TDI)

This input pin is sampled on the rising edge of TCK. TDI is the data to be shifted toward the TDO output.

Test Data Output (TDO)

This 3-state output pin changes its logical value on the falling edge of TCK.

Test Reset ($\overline{\text{TRST}}$)

This input pin is the JTAG asynchronous reset. When asserted low, the test access port is forced to the Test_Logic_Reset state. When JTAG is not being used, this signal should be tied to $\overline{\text{ARST}}$ or hard-wired to GND.

6. INGRESS DATA PATH OPERATION

6.1 Ingress Data Path

The ingress data path includes the following steps:

1. Cell assembly from physical layer
2. Address compression
3. Context Table lookup
4. Cell counting
5. UPC/NPC processing
6. Cell insertion
7. OAM processing
8. Appending switch overhead information and address translation
9. Transfer to switch

The cell flow through these steps is shown in **Figure 8**. Each step is described in the subsections below. During the processing, the decision can be made to remove a cell from the cell flow based on the connection parameters or the OAM processing, among other reasons. Such a cell may be copied to the cell extraction queue.

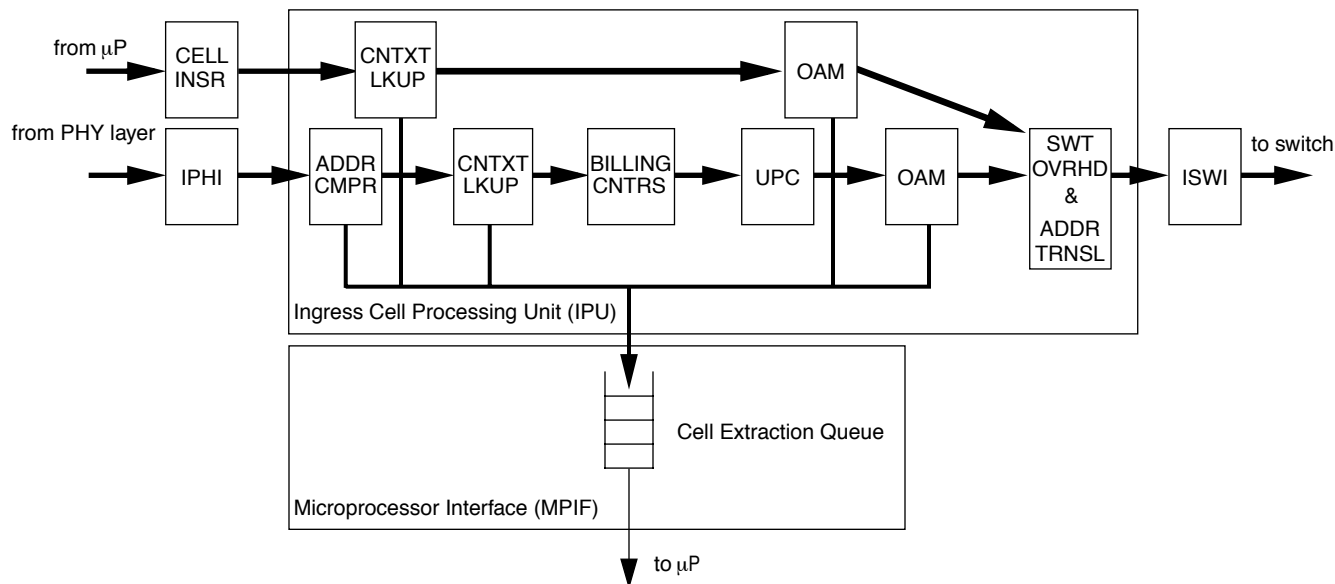


Figure 8. Ingress Data Path

6.2 Interface to Physical Layer - Cell Assembly

The Ingress Physical-Layer Interface (IPHI) block receives cell data from the physical layer using the UTOPIA standard interface. The bytes are assembled into cells since the MC92500 processing is on a cell basis. The cells are held in a FIFO and are read one cell per cell slot by the cell processing block.

The input data pins are parity protected. Parity checking by the MC92500 is optional. When parity checking is enabled, the MC92500 expects RXPATY to contain odd parity over RXDATA.

The Header Error Correction (HEC) received from the

physical layer is not checked by the MC92500, and it is discarded from the cell.

Since the MC92500 processes cells at a higher rate than they are received from the physical layer, the IPHI block cannot assemble a cell during every cell processing slot. When no complete cell is available, the IPHI block informs the Ingress Cell Processing block (IPU), and a hole is inserted in the cell flow through the MC92500.

The IPHI block checks the cell header and recognizes the “unassigned” and “invalid” header values defined in [Table 1](#) and [Table 2](#).

Table 1. Pre-assigned Header Values at the UNI

Use	GFC	VPI	VCI	PTI	CLP
Unassigned cell	XXXX	00000000	00000000 00000000	XXX	0
Invalid pattern at the ATM layer	XXXX	00000000	00000000 00000000	XXX	1

X= don't care bit

Table 2. Pre-assigned Header Values at the NNI

Use	VPI	VCI	PTI	CLP
Unassigned cell	0000 00000000	00000000 00000000	XXX	0

X= don't care bit

6.3 Address Compression

The purpose of the ingress address compression is to map the address field(s) in the header of the received cell into a pointer to the entry in the Context Table that relates to the cell's virtual connection. The MC92500 supports two types of service, Virtual Path switching service and Virtual Channel switching service. For VP switching the address is the Virtual Path Identifier (VPI) field of the cell header. For VC switching the address consists of both the VPI and the Virtual Channel Identifier (VCI) fields of the cell header.

When the MC92500 supports multiple PHY layer devices, the mapping of ATM addresses to Context Table entries must be done separately for each PHY layer link. For this purpose, the number of the link from which a cell arrived can be treated as an additional address field. In this case, a VP switching address consists of the Link/VPI fields and a VC switching address consists of the Link/VPI/VCI fields.

Cells that are inactive, i.e. for which no valid connection is found during address compression, are removed from the cell flow and copied to the Cell Extraction Queue.

Address Compression Options

The MC92500 supports two methods for performing address compression:

1. Table lookup using restricted address spaces
2. External address compression

Table Lookup

When some of the bits of the VPI and/or VCI are not allocated, the address range can be reduced enough to make a table lookup scheme practical.

External Address Compression

The external address compression method allows the user total flexibility in performing the ingress address compression.

6.4 Cell Counting

If the processed cell was received from the physical layer (not inserted internally), one of the existing connection cell counters from the Ingress Billing Counters Table and one of the existing link cell counters from the Ingress Link Counters Table is incremented. The appropriate counter is chosen based on the CLP bit and whether the cell is an OAM cell.

UPC/NPC

One of the major advantages of ATM is the ability to dynamically distribute the available bandwidth among many connections. However, it is this feature that makes congestion in an ATM network difficult to predict. In order to make the network management feasible, limits are imposed on the traffic parameters of each connection. Typically, the maximum average bandwidth and the maximum burstiness may be defined.

Even when the usage parameters have been defined, a single user that does not stick to the agreed-upon parameters can cause congestion which will lead to a reduction in the quality of service provided to the other users. Therefore, the usage parameters should be enforced at the entrance to the network in such a way that the violating user is the one who suffers reduced quality of service. This enforcement is called Usage Parameter Control (UPC) at a User-Network Interface (UNI) and is called Network Parameter Control (NPC) at a Network-Network Interface (NNI).

The MC92500's UPC/NPC algorithm, based on the concept of "leaky buckets", detects cells that violate the traffic agreement and optionally tags (i.e. changes CLP-field from 0 to 1) or discards (removes from the cell flow) violating cells. A flexible arrangement of leaky buckets (0 to 4 per connection), leaky bucket parameters and UPC/NPC enforcement algorithms is provided for all connections. At connection set-up time a set of bucket characteristics is loaded into the Bucket Table section of context memory. This defines the expected cell arrival pattern on a particular connection, and it is used by the UPC/NPC function as a means of enforcing the agreed-upon user traffic.

Note: For constant bit rate and variable bit rate connections the bucket characteristics are normally defined when the connection is setup and remain constant. However, other types of connections may require dynamic UPC/NPC enforcers where the processor updates these values while the connection is active. Caution is advised when doing so in order to maintain consistency among the various parameters of the enforcer.

All user data cells that have not been removed from the cell flow are subject to UPC/NPC processing according to the parameters of their connection. Counts of the cells that have been discarded or tagged are optionally maintained per connection in the Ingress Policing Counters Table.

A “don’t touch” option is provided to apply the UPC/NPC algorithm for statistical purposes without tagging or discarding the violating cells.

A UPC/NPC mechanism can be used to enforce the sum of several connections. This method is likely to be used at the boundary point where many VCCs are combined into a VPC.

6.5 Ingress Cell Insertion

The MC92500 makes use of the holes in the cell flow provided by the IPHI block (whether due to the difference between the cell processing and arrival rates or the reception of unassigned or invalid cells) to insert cells into the ingress cell flow. The cell insertion rate is paced by a single leaky bucket to ensure that the switch is not flooded with inserted cells beyond its capacity.

The types of cells that can be inserted in the ingress cell flow are:

- OAM cells generated internally by the MC92500 including:
 - AIS cells
 - RDI cells
 - Continuity Check cells
 - PM Forward Monitoring cells
- OAM cells generated by the microprocessor
- Other cells generated by the microprocessor

The various types of cells that can be inserted in the ingress cell flow are classified by their insertion priority and held in separate queues. The insertion priorities are (from highest to lowest):

1. PM Forward Monitoring cells generated internally by the MC92500
2. Cells from the microprocessor
3. AIS, RDI, and CC cells generated internally by the MC92500

6.6 Switch Overhead Information

The MC92500 optionally performs address translation on the Ingress cell flow. The new address fields are taken from the Ingress Translation Address word of the Context Parameter Table in the External Memory.

The source of the switch overhead information provided by the MC92500 is the Context Parameters Table entry for the connection. The overhead bytes are transferred before the cell, most-significant byte first. If any of the switch parameter words are not provided, the values of the corresponding overhead bytes added to the cell are undefined. The MC92500 can add up to 16 bytes of switch overhead information.

6.7 Transfer to Switch

The Ingress Switch Interface (ISWI) block receives cells from the Cell Processing block, queues them, and transfers the data structure to the switch.

The switch interface signals are identical to the UTOPIA Level 1 Receive Interface with the MC92500 playing the role of the PHY layer and the switch playing the role of the ATM layer. The switch interface signals are clocked by an independent clock signal, SRXCLK. The switch is required to accept cells from the MC92500 when they are presented on the interface with a delay of up to one cell slot for synchronization. Note that the cells may be presented at a higher rate than they are received from the PHY layer due to cell insertion. The switch must be capable of receiving the cells at a sustained rate of one cell per cell slot. Otherwise, the cells may back up in the MC92500, processing will be halted, and cells will not be accepted from the PHY layer. Although the maximum sustained rate is one cell per cell slot, the rate can be limited by the insertion pacing mechanism.

7. EGRESS DATA PATH OPERATION

7.1 Egress Data Path

The egress data path includes the following steps:

1. Transfer from switch
2. Multicast identifier translation (if necessary)
3. Cell insertion
4. Context Table lookup
5. OAM processing
6. Address translation

7. Cell Counting
8. Transmission to the physical layer

The cell flow through these steps is shown in [Figure 9](#). Each step is described in the subsections below. During the processing, the decision can be made to remove a cell from the cell flow for any of several reasons. Such a cell may be copied to the Cell Extraction Queue.

7.1.1 Transfer from Switch

The Egress Switch Interface (ESWI) block contains a cell FIFO. Data is received from the switch at the rate of one byte per clock cycle. The data structure received from the switch includes overhead routing information in addition to the ATM cell. When a full cell has been transferred, it is transformed into an internal data structure and presented to the Egress Cell Processing block.

The switch interface signals are identical to the UTOPIA Level 1 Transmit Interface with the MC92500 playing the role of the PHY layer and the switch playing the role of the ATM layer. The switch interface signals are clocked by an independent clock signal, STXCLK.

The input signal STXSOC is used to delineate the beginning of a cell.

The input data pins are parity protected. If a parity error is detected on the input pins, the error is reported. If the parity error occurs on a byte containing any of the overhead fields used by the MC92500 or on a byte of the cell header, the cell is discarded. If the parity error occurs on a payload byte, the cell is optionally discarded.

If a protocol error is detected on the input pins, the current cell is discarded and the error is reported.

The ESWI block contains a small cell FIFO to assemble the bytes received from the switch and synchronize the cells to the cell processing time of the Egress Cell Processing block. The size of the FIFO is programmable to either 4 or 6 cells. The FIFO is read by the Cell Processing block at a rate which is limited by the PHY

layer and by cell insertion. When the ESWI FIFO is full, the MC92500 refuses to accept a cell from the switch by negating STXCLAV.

The number of bytes in the cell data structure received from the switch is programmable.

The bytes are provided by the switch in the following order:

1. Overhead bytes
2. ATM Cell Header (4 bytes; PTI, CLP valid; VCI valid if VP switching)
3. HEC octet (provided only if ESHF is set) - this octet may be used for overhead information since no HEC value is stored in the internal data structure
4. ATM cell payload (48 bytes)

The fields that are contained in the overhead bytes are:

- Egress Connection Identifier (ECI) / Multicast Identifier (MI)
- Multicast bit (M)
- Explicit Forward Congestion Indication (EFCI)
- Multicast Translation Table Section (MTTS)

The location of these fields in the overhead, header and HEC bytes is programmable. Once the valid fields have been retrieved, the remaining overhead bytes received from the switch will be discarded since they are of no use to the MC92500 and are not transferred to the PHY layer.

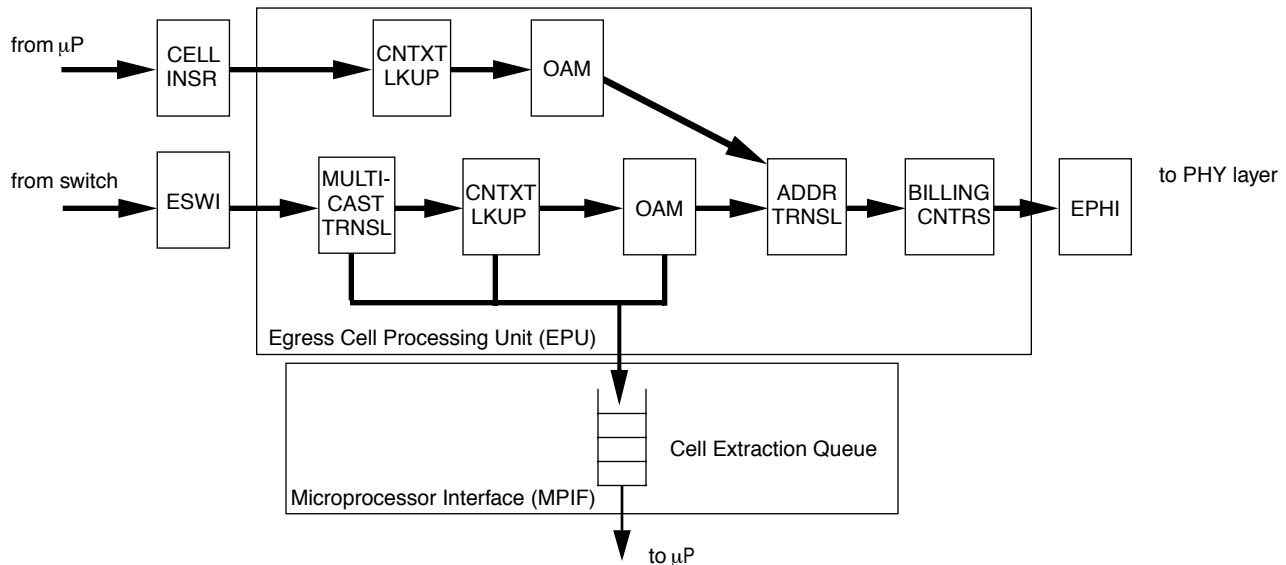


Figure 9. Egress Data Path

7.1.2 Multicast Identifier Translation

Multicasting involves copying a cell that arrived at the switch and transmitting it on multiple physical links. In the general case the ECI of the connection to which the cell belongs will be different on each link. If the switch can provide the correct ECI to each MC92500 device, the multicast operation is transparent to the MC92500. However, if the switch cannot provide separate ECIs for each link, a common multicast identifier may be provided to all of the MC92500 devices. Each MC92500 will translate the multicast identifier into the ECI for its physical link.

7.1.3 Egress Cell Insertion

In order to insert cells into the egress cell flow, the MC92500 creates holes in the cell flow received from the switch interface block by not taking a cell from the FIFO. Inserting many cells in a short period of time may overload the switch’s queuing capability. Therefore, the cell insertion rate is regulated by a leaky bucket.

The types of cells that can be inserted in the egress cell flow are:

- OAM cells generated internally by the MC92500 including:
 - AIS cells
 - RDI cells
 - Continuity Check cells
 - PM Forward Monitoring cells
- OAM cells generated by the microprocessor
- Other cells generated by the microprocessor

The various types of cells that can be inserted in the egress cell flow are classified by their insertion priority and held in separate queues. The insertion priorities are (from highest to lowest):

1. PM Forward Monitoring cells generated internally by the MC92500
2. Cells from the microprocessor
3. AIS, RDI, and CC cells generated internally by the MC92500

7.1.4 Address Translation

The address fields of the cell header are optionally replaced by the outgoing address of the outgoing link as read from the Egress Translation Address word of the Context Parameter Table. If the cell belongs to a VPC, only the VPI field is replaced. If the cell belongs to a VCC, both the VPI and VCI fields are replaced.

The MC92500 sets the middle bit of the PTI on cells whose received PTI is 000 or 001 when the EFCI bit received from the Egress switch interface block is set.

7.1.5 Cell Counting

For each cell transmitted to the PHY layer, one of the counters from the Egress Billing Counters Table for this connection is incremented, unless the table does not exist. One of the link cell counters from the Egress Link Counters Table is also incremented if the table exists. The appropriate counter is chosen based on the CLP bit and whether the cell is an OAM cell. Cells that are removed from the cell flow are not included in the usage counts. Inserted cells and internally generated cells are included in the usage counts.

7.1.6 Transmission to Physical Layer

The Egress Physical-Layer Interface (EPHI) block receives cells from the Cell Processing block, queues them, and transmits the cell data to the physical layer using the UTOPIA standard interface.

The cells are then stored in a FIFO and are disassembled into bytes for transmission to the physical layer. The size of the FIFO is programmable to either 2 or 4 cells. If the EPHI FIFO is empty, the MC92500 optionally fills the hole with a cell to provide a continuous cell flow at the physical layer bit rate. The type of cell used to fill the holes is either “unassigned” (an ATM layer cell) or “Idle” (a physical layer cell). If multiple physical links are supported, the generation of these cells is not supported and should not be enabled.

Since the MC92500 processes cells at a higher rate than they are transmitted to the physical layer, the EPHI block cannot transfer a cell during every cell processing slot. Over time, cells may accumulate in the EPHI FIFO until it is full. When this happens, the MC92500 will not process a cell during the next cell processing slot, allowing the FIFO to drain to the physical layer.

TXPRTY is always driven with odd parity over TXDATA, regardless of whether or not parity checking is enabled on the Ingress PHY Interface.

The fifth octet of the transmitted cell (the HEC field) is always transmitted as zero, regardless of the value passed to the MC92500 by the switch interface block.

8. SYSTEM OPERATION

8.1 MC92500 Modes of Operation

The MC92500 has two basic modes of operation, Setup and Operate. After reset, the MC92500 is in Setup Mode. Switching to Operate Mode is accomplished by writing to a pseudo-register.

8.1.1 Setup Mode

The MC92500 enters Setup Mode after reset. This mode of operation is used to configure the MC92500 and to initialize the external (context) memory. While in Setup Mode, the MC92500 does not use the External Memory, in order to provide the microprocessor and/or DMA device with unrestricted access to the External Memory. Additionally, those registers identified as configuration registers may be written only when the MC92500 is in Setup Mode. A write access to any of these registers in Operate Mode is forbidden.

When the MC92500 is in Setup Mode, the Receive PHY Interface is disabled by keeping the \overline{RXENB} output signal negated. No cells are read from the Egress switch interface block. The Egress Switch Interface is disabled by keeping STXCLAV negated. Cell insertion is not allowed in Setup Mode.

Once the MC92500 has switched from Setup Mode to Operate Mode, it will not return to Setup Mode until a hardware or software reset is performed.

8.1.2 Operate Mode

While in Operate Mode, the MC92500 processes the cells received from the PHY layer and the switch interface block. The configuration registers may be read, but not written, when the MC92500 is in Operate Mode.

8.1.3 Reset

The MC92500 can be reset in either of two ways: hardware reset by asserting the MC92500 Power-Up Reset (\overline{ARST}) pin or software reset by writing to the Software Reset Register (SRR). In either case all the internal registers will be loaded with their default values. The reset process requires 200 ACLK cycles or 200 MCLK cycles, whichever is greater, after the negation of \overline{ARST} or the write to the SRR. During this time, writing to the MC92500 registers is not allowed. At the conclusion of the reset, the MC92500 will be in setup mode.

When a write access to the SRR is performed, the MC92500 begins the reset process only after writing the results of the current cell processing to External Memory. In this way the External Memory remains consistent, and it is not necessary to re-initialize the External Memory when performing a software reset of the MC92500.

8.2 Data Path Clock Configuration

The MC92500 is designed such that the PHY data path interfaces operate using the same clock. The UTOPIA standard requires the ATM layer to provide the interface clocks, RxClk and TxClk. Since the IPHI and EPHI interfaces use ACLK, the clock provided to the MC92500, this same clock should be connected to the RxClk and TxClk pins of the PHY component. Therefore, these clock signals of the UTOPIA interface are not explicitly provided by the MC92500. The switch interfaces are independently clocked by the clock signals connected to the SRXCLK and STXCLK pins. This configuration is shown in Figure 10.

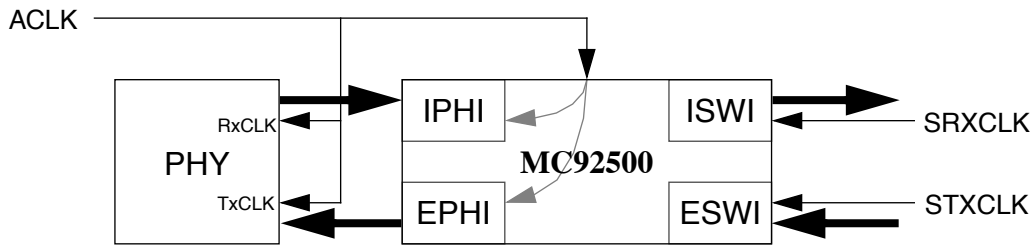


Figure 10. MC92500 Clock Configuration

9. ELECTRICAL CHARACTERISTICS

9.1 Electrical Specifications

9.1.1 Clocks

Num	Characteristics	Min	Max	Unit
C1	ACLK Cycle Time	39	80	ns
C2	ACLK Pulse Width Low	15		ns
C3	ACLK Pulse Width High	15		ns
C4	ACLK Rise/Fall Time		5	ns
C5	MCLK Cycle Time	30		ns
C6	MCLK Pulse Width Low	12		ns
C7	MCLK Pulse Width High	12		ns
C8	MCLK Rise/Fall Time		5	ns
C9	SRXCLK/STXCLK Cycle Time	30		ns
C10	SRXCLK/STXCLK Pulse Width Low	12		ns
C11	SRXCLK/STXCLK Pulse Width High	12		ns
C12	SRXCLK/STXCLK Rise/Fall Time		5	ns

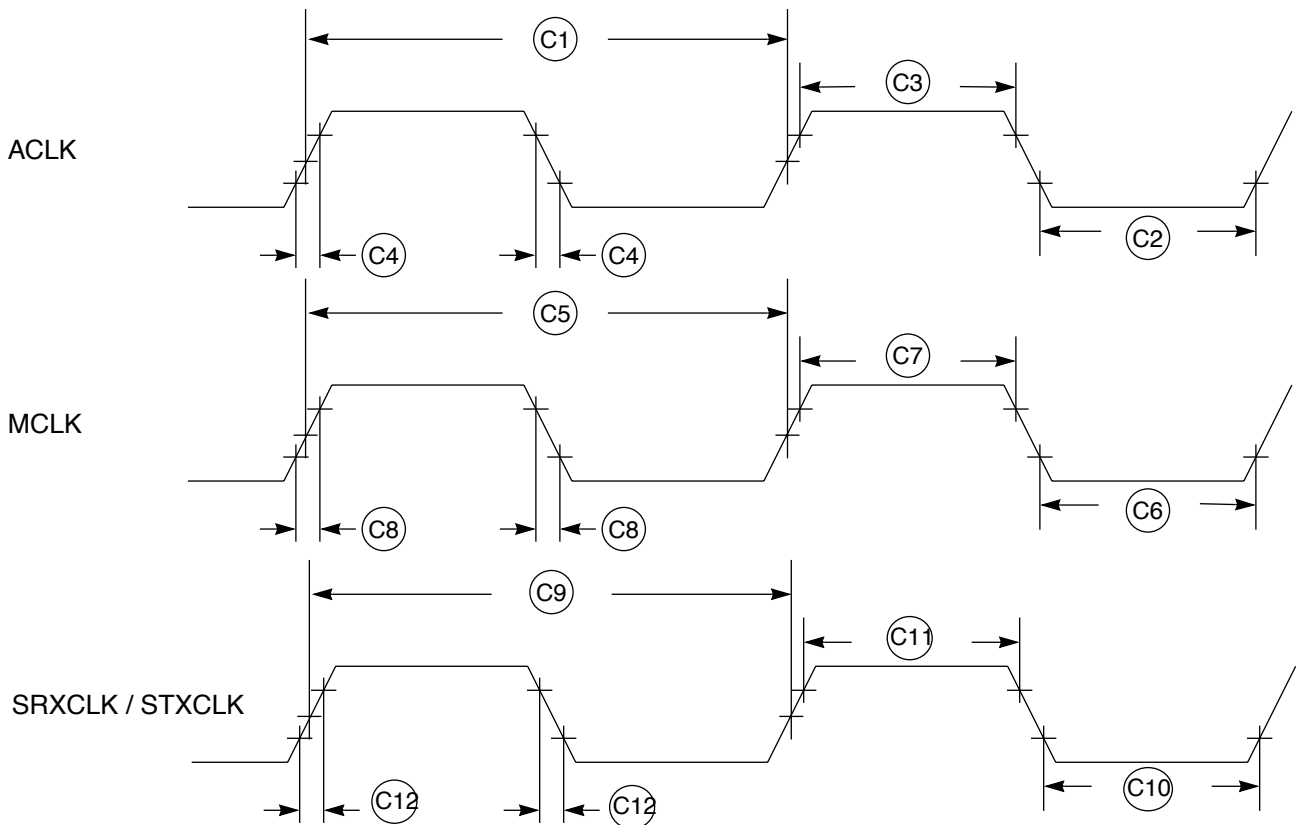


Figure 11. Clocks Timing

9.1.2 Microprocessor Interface Timing

The timing diagrams in this section are intended to convey setup and hold values for input signals and propa-

gation delay values for output signals. The diagrams are NOT intended to convey cycle based behavior.

Num	Characteristics	Min	Max	Unit
1	MSEL setup time before MCLK falling edge	5		ns
2	MSEL hold time after MCLK falling edge	1		ns
3	MADD/MWR setup time before MSEL assertion	5		ns
4	MADD/MWR hold time after MCLK falling edge ^a	3		ns
5	MDS setup time before MCLK falling edge	5		ns
6	MDS hold time after MCLK falling edge	1		ns
7	MDATA setup time before MCLK falling edge	4		ns
8	MDATA hold time after MCLK falling edge	1		ns
9	MSEL assertion to MDATA active	0		ns
11	MCLK falling edge to MDATA valid for CER Accesses ^b		26	ns
12	MSEL negation to MDATA invalid	1		ns
13	MSEL negation to MDATA inactive		11	ns
14	MWR assertion to MDATA invalid	1		ns
15	MWR assertion to MDATA inactive		11	ns
16	MCLK rising edge to MDATA valid for Maintenance Accesses ^{b, c}		T _D	ns
17	MCLK falling edge to MDATA valid for General Register Accesses ^{b, d}		T _R	ns
19	MSEL assertion to MDTACK active	0		ns
20	MCLK falling edge to MDTACK inactive		12	ns
21	MSEL assertion to MDTACK asserted ^e		9	ns
22	MSEL negation to MDTACK negated ^e		13	ns
23	MCLK rising edge to MDTACK asserted ^e		13	ns
24	MWSH, MWSL setup time before MCLK falling edge ^a	2		ns
25	MWSH, MWSL hold time after MCLK falling edge ^a	3		ns
26	MCLK falling edge to REQ valid	0	14	ns
27	MCLK falling edge to MDTACK asserted for General Register Read Accesses ^{e, f}		T _{RD}	ns
28	MCLK falling edge to MDTACK asserted for General Register Write Accesses ^{e, g}		T _{WD}	ns
29	Access width (MCLK falling edge to MSEL negation) for General Register Write Accesses ^h		T _W	ns

a. refers only to the first falling edge of MCLK in each access at which MSEL is asserted

b. This is for a 150 pF load. Add 0.9 ns for each additional 10 pF. For a 100 pF load, subtract 4 ns.

c. T_D = External Memory access time + 18 ns

d. T_R = 4 * ACLK period + 20 ns

e. This is for a 50 pF load.

f. T_{RD} = 4 * ACLK period + 11 ns

g. T_{WD} is measured from the MCLK falling edge at which MDS is sampled as asserted. T_{WD} = 4 * ACLK period + 11 ns

h. T_W is measured from the MCLK falling edge at which MDS is sampled as asserted. T_W = 4 * ACLK period. Note that the setup and hold times with respect to MCLK (timing values 1 and 2) still apply.

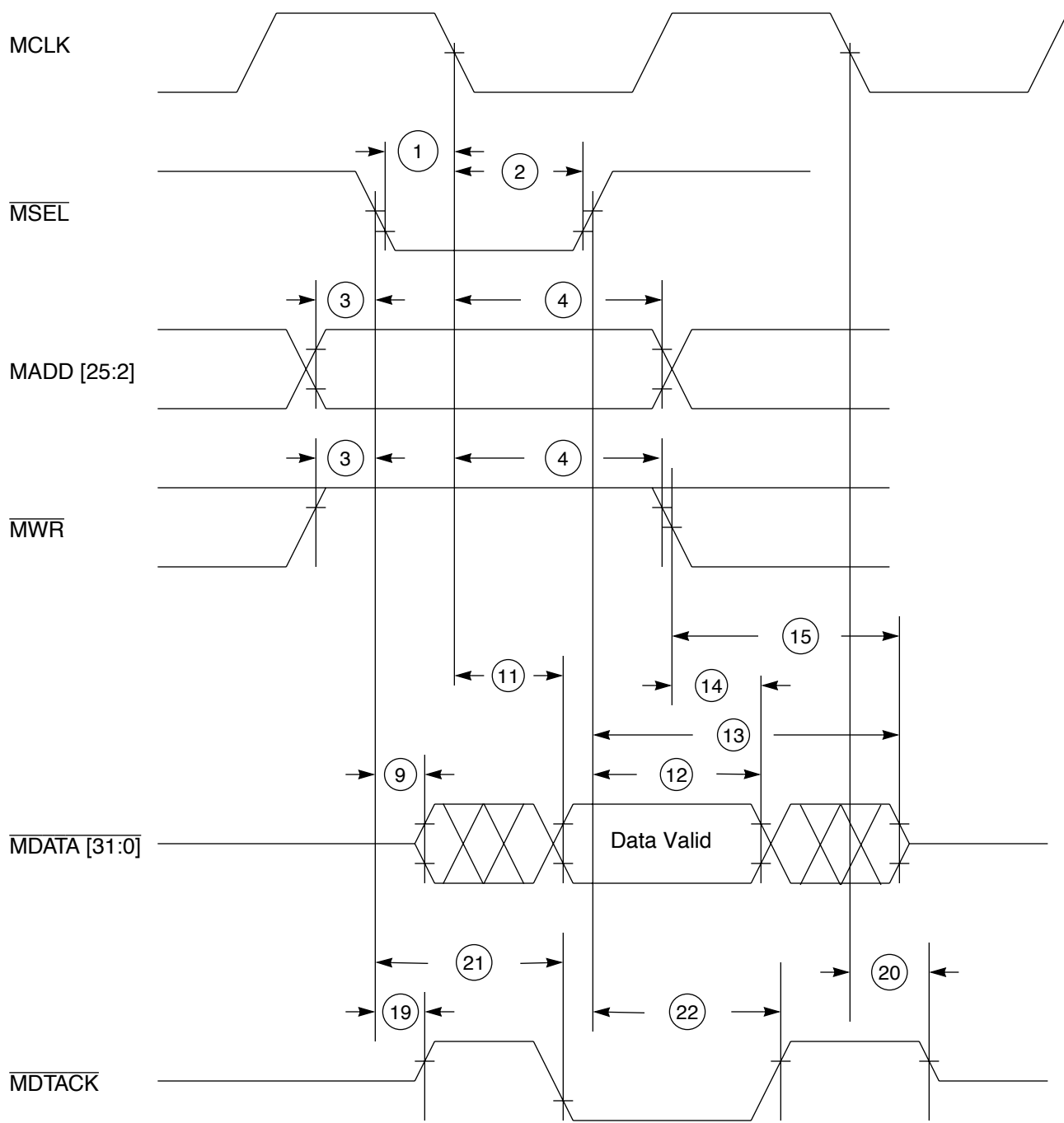


Figure 12. Cell Extraction Register Read Access Timing

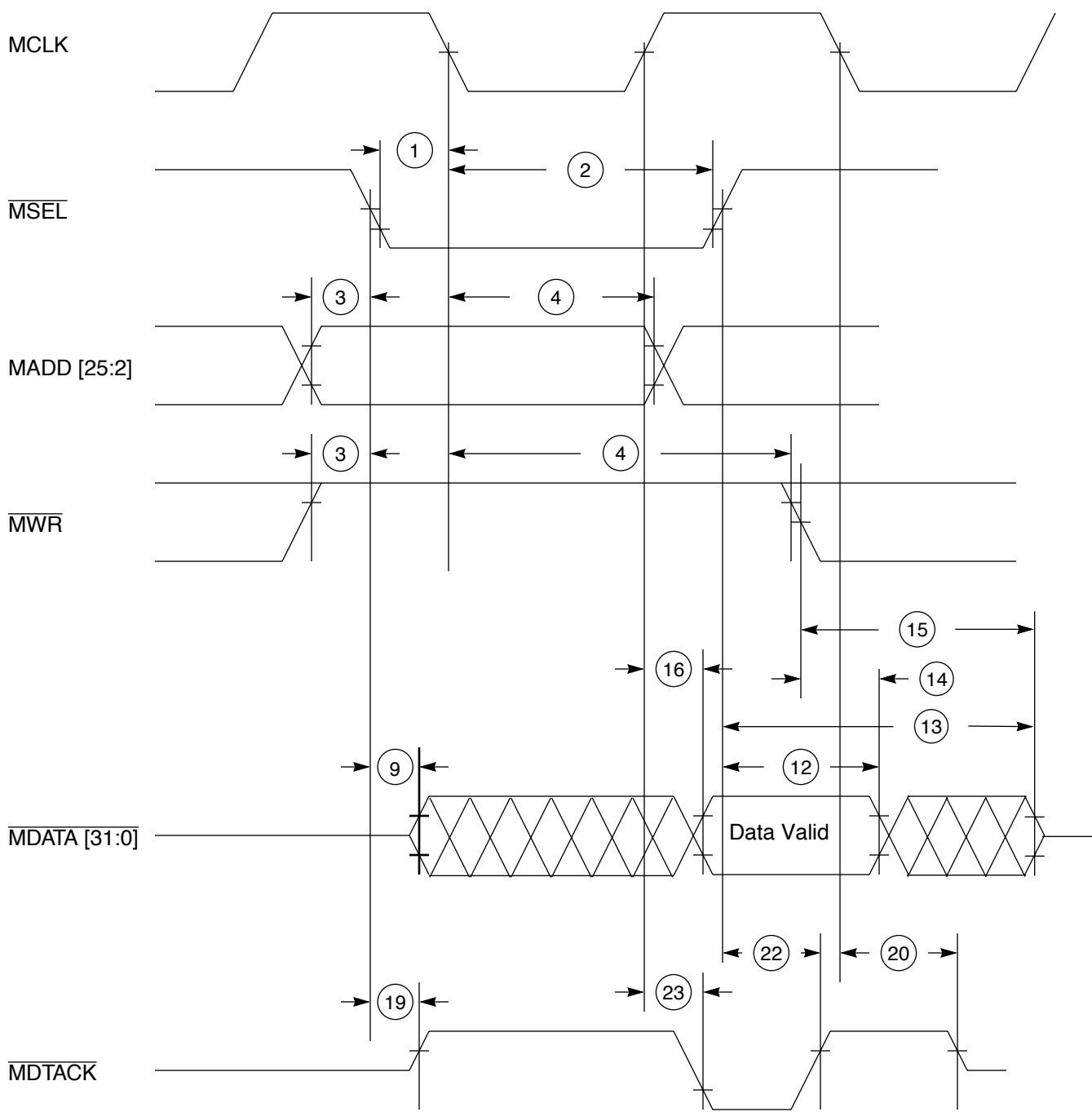


Figure 13. Maintenance Read Access Timing

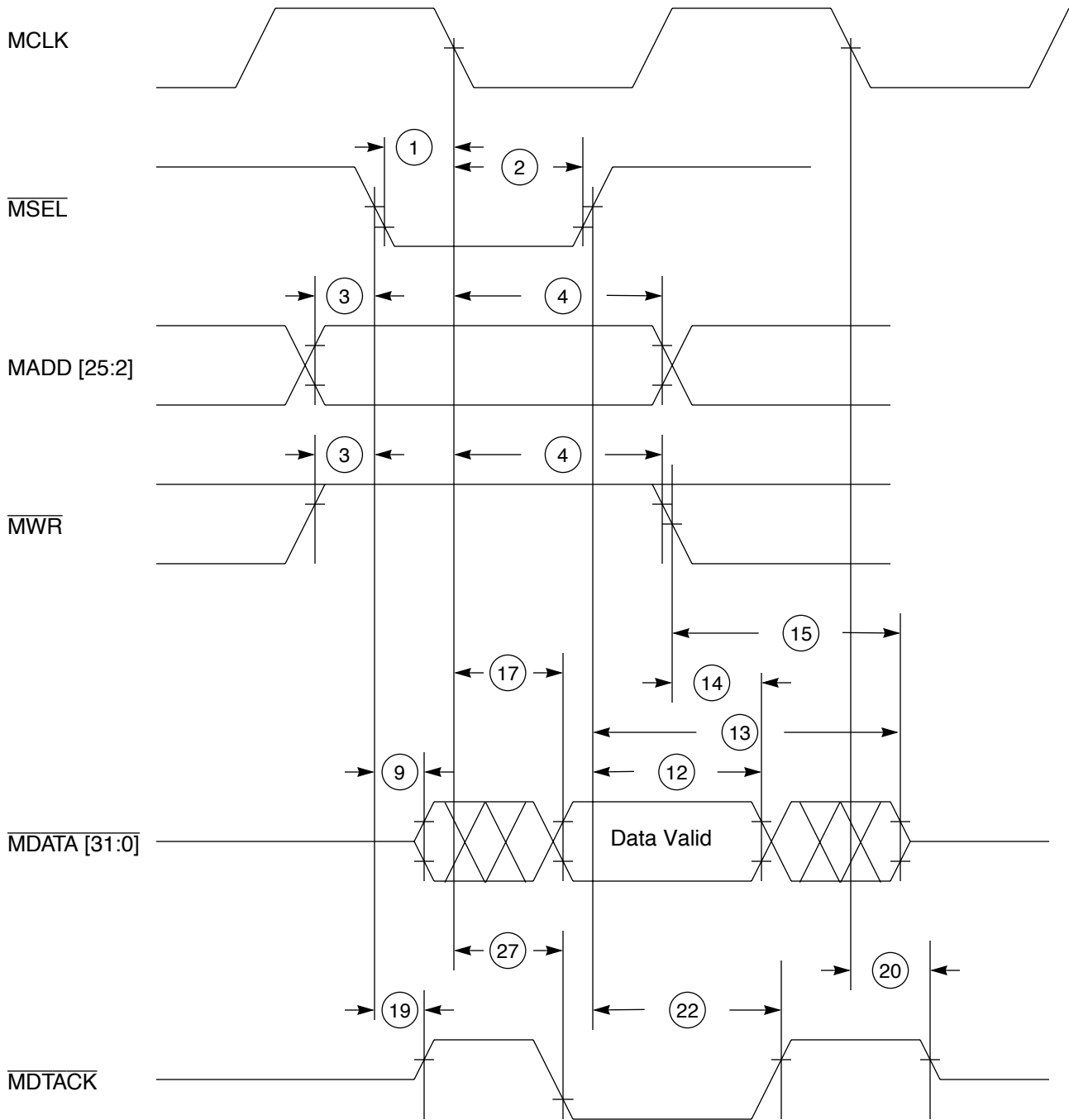


Figure 14. General Register Read Access Timing

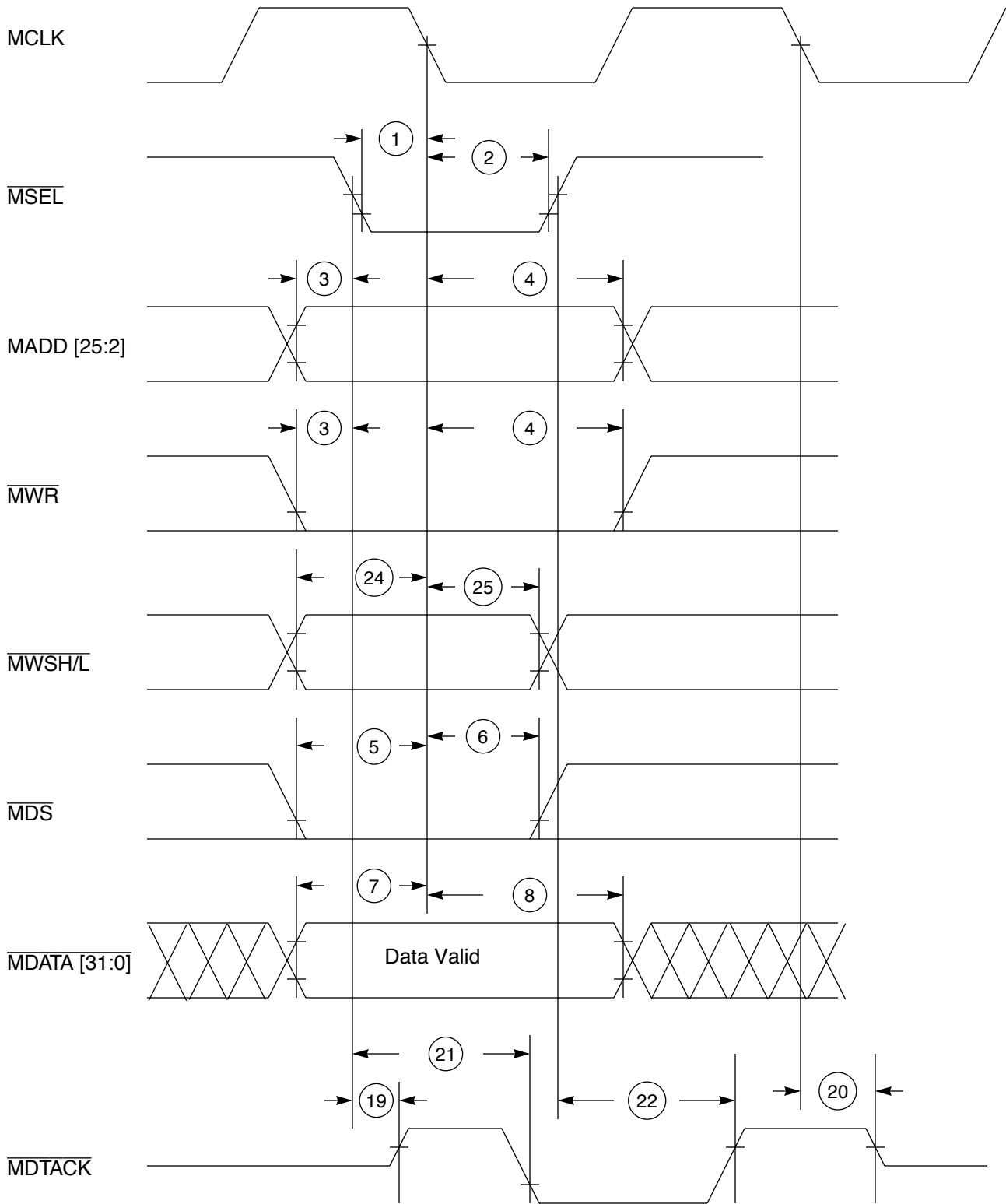


Figure 15. Cell Insertion Register Write Access / Maintenance Write Access Timing

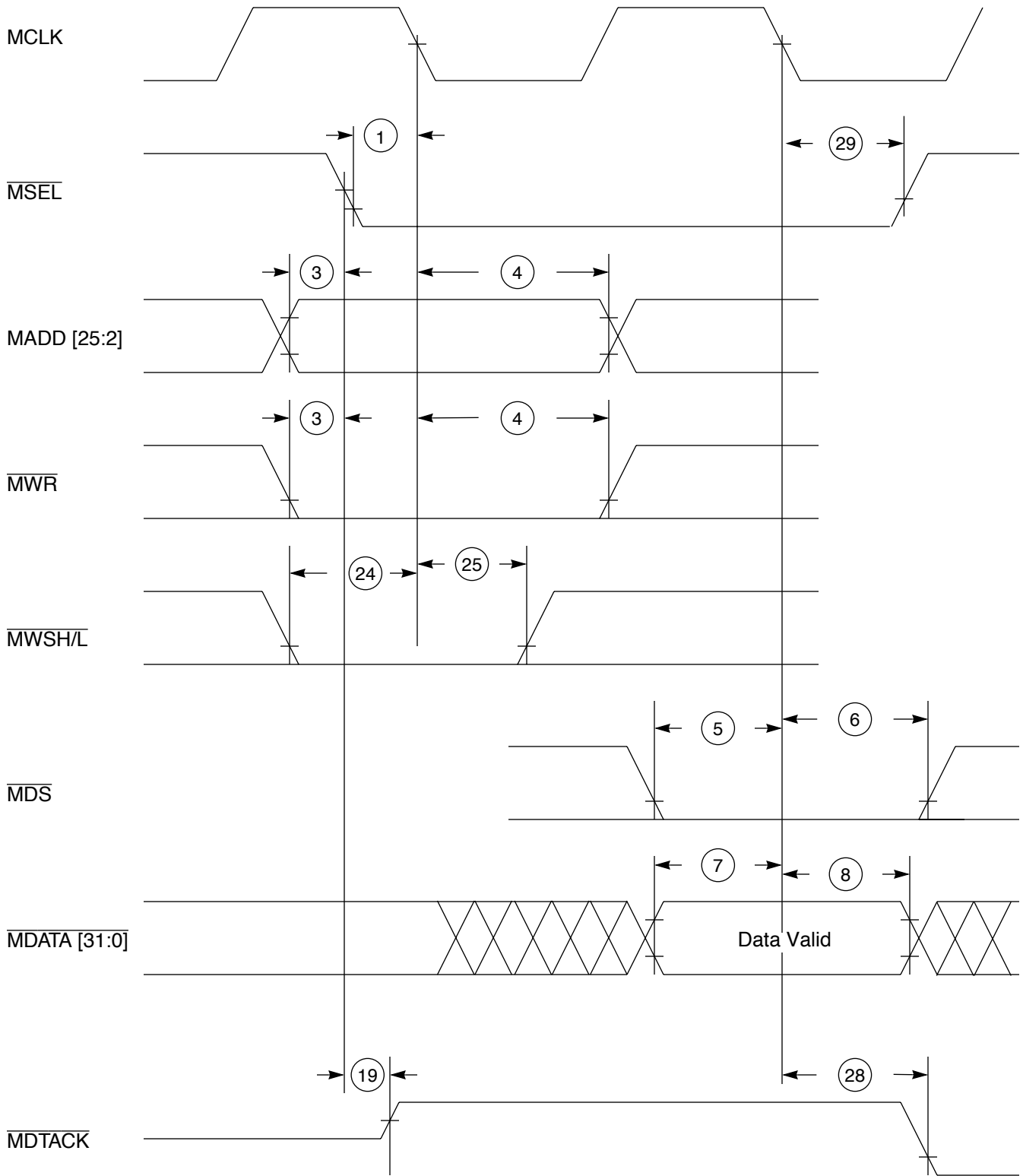


Figure 16. General Register Write Access Timing

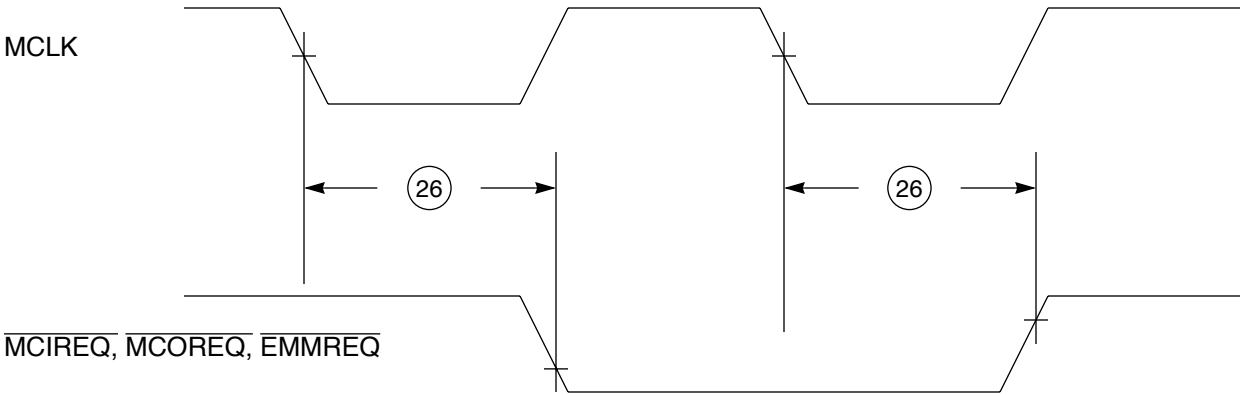


Figure 17. DMA Request Signals Timing

Freescale Semiconductor, Inc.

9.1.3 PHY Interface Timing

Num	Characteristics	Min	Max	Unit
51	setup time before ACLK rising edge	10		ns
52	hold time after ACLK rising edge	1		ns
53	propagation delay from rising edge of ACLK	1	16	ns

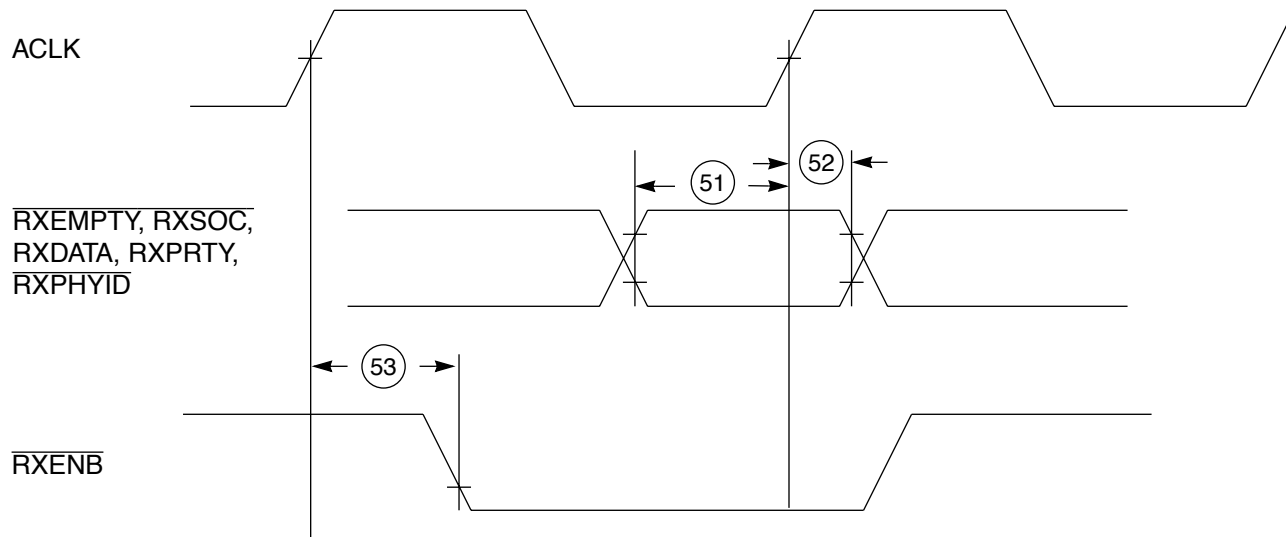


Figure 18. Receive PHY Interface Timing

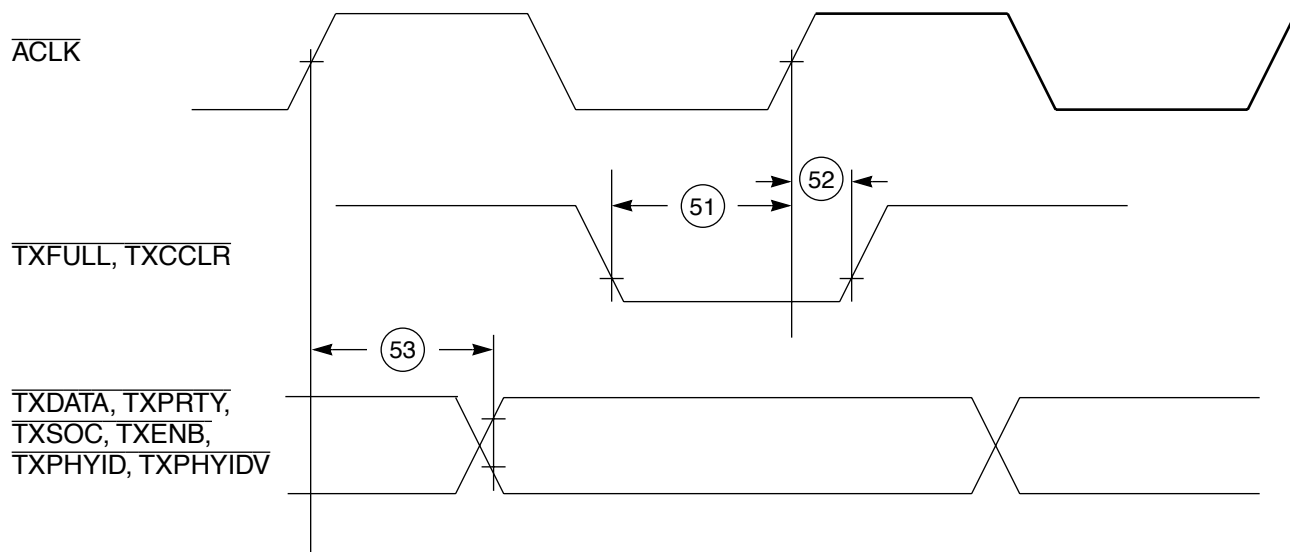


Figure 19. Transmit PHY Interface Timing

9.1.4 Switch Interface Timing

Num	Characteristics	Min	Max	Unit
61	setup time before SRXCLK/STXCLK rising edge	4		ns
62	hold time after SRXCLK/STXCLK rising edge	1		ns
63	propagation delay from rising edge of SRXCLK/STXCLK	1	18	ns
64	SRXCLK rising edge to outputs active	1		ns
65	SRXCLK rising edge to outputs inactive	1	16	ns

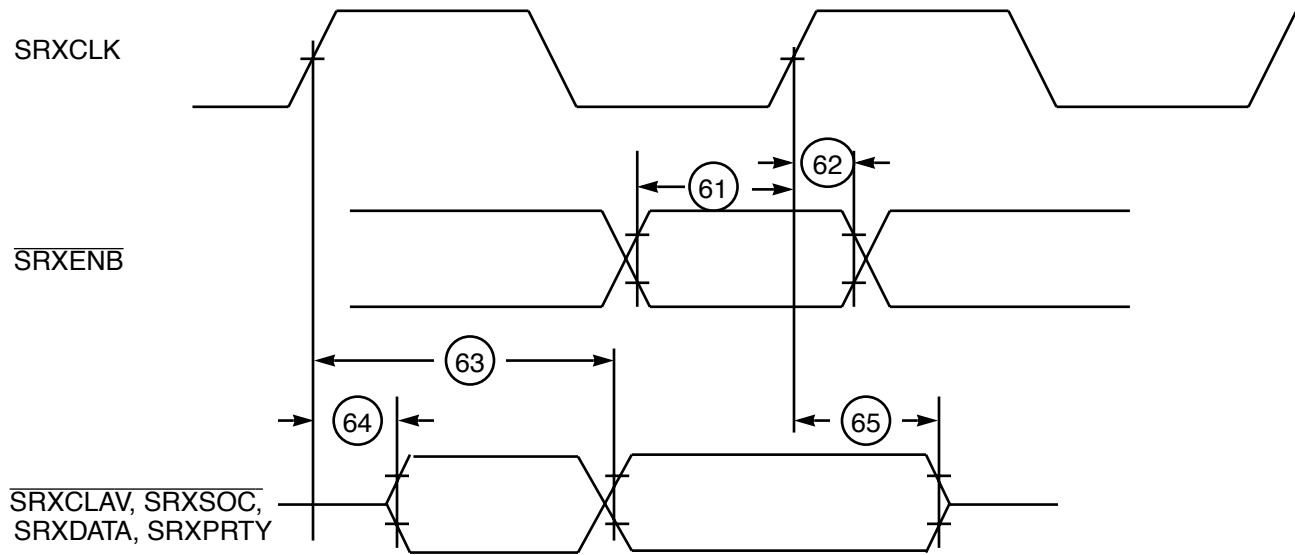


Figure 20. Ingress Switch Interface Timing

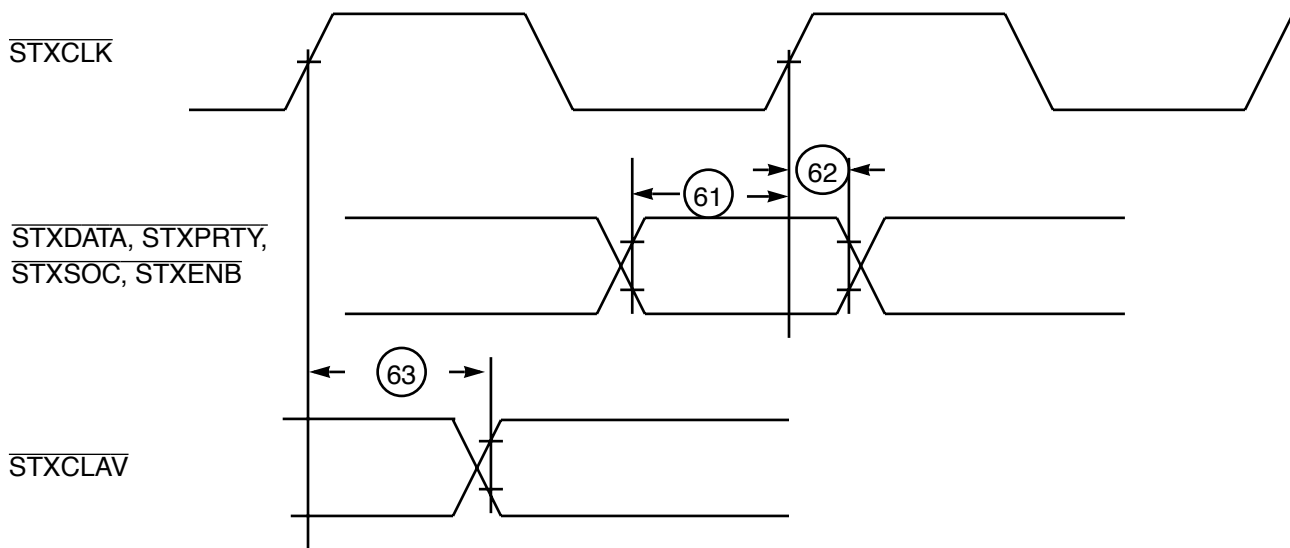


Figure 21. Egress Switch Interface Timing

9.1.5 External Memory Interface Timing

This section represents External Memory timing parameters for the default definition. These values are for

a load of up to 50 pF, which is the rated maximum load for the External Memory interface pins.

9.1.6 Write Cycle Timing

Num	Characteristics	Min	Max	Unit
81	Write Pulse Width ^a .	16		ns
82	$\overline{\text{EMWR}}$ assertion time. $\overline{\text{EMWR}}$ low to end of Write ^a .	22		ns
83	Address Setup Time. EMADD Valid to Beginning of Write ^a .	6		ns
84	Address Valid Time. During this Time EMADD is Valid.	32		ns
85	Address Hold Time. End of Write ^a to EMADD Invalid.	6		ns
87	Data Setup Time. EMDATA Valid to End of Write ^a .	13		ns
88	Data Hold Time. End of Write ^a to EMDATA Invalid.	6		ns

a. A write occurs during the overlap of $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ low and $\overline{\text{EMWR}}$ low.

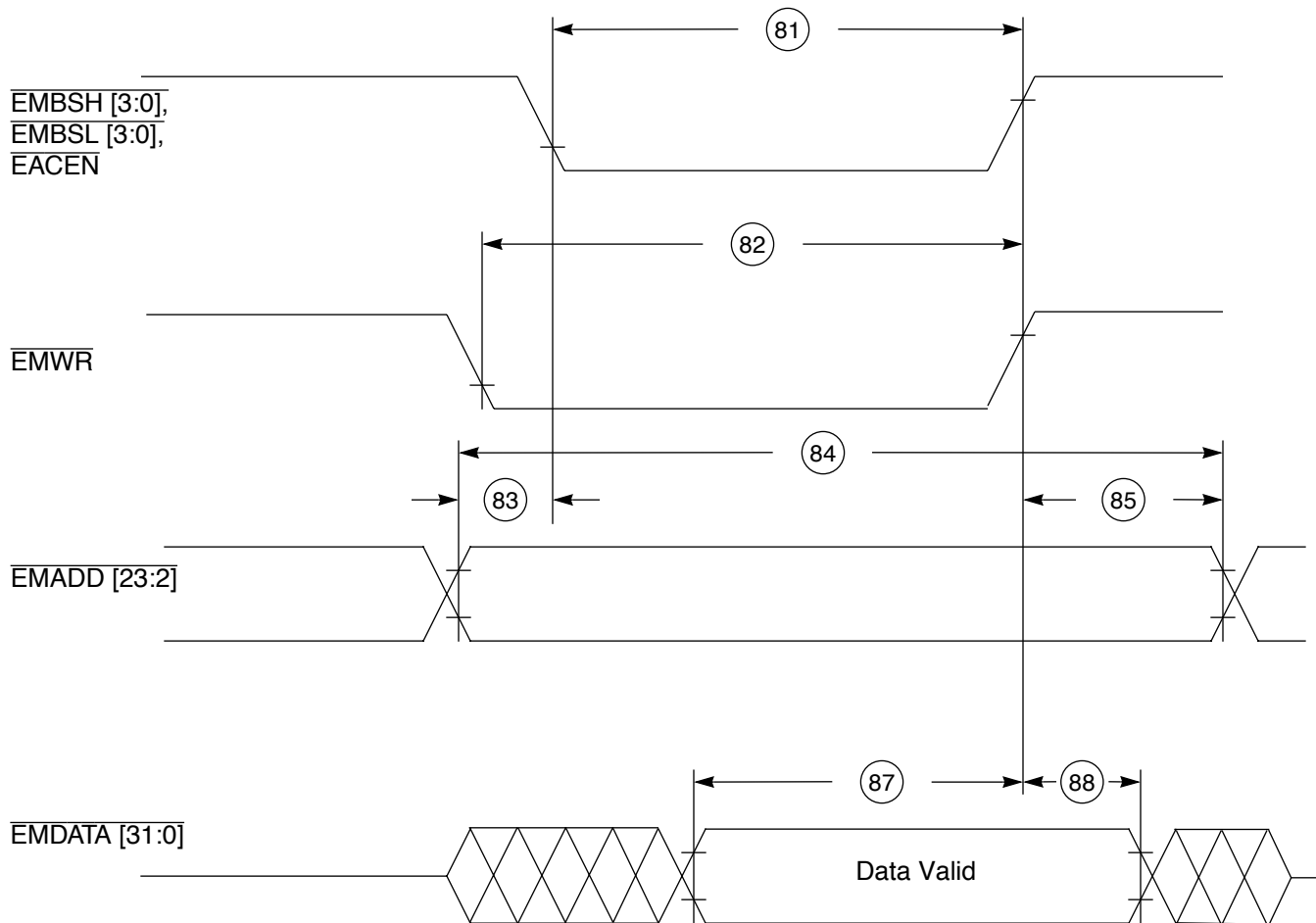


Figure 22. External Memory Write Access Timing

9.1.7 Read Cycle Timing

Num	Characteristics	Min	Max	Unit
90	Enable Pulse Width. $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ Pulse Width.	28		ns
92	Address Setup Time. $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ High.	33		ns
93	Address Hold Time. EMADD Invalid to $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ High		1 _a	ns
94	Data Driving Start Point. $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ Low to EMDATA Active.	0		ns
95	Data Setup Time. EMDATA Valid to $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ High.	5		ns
96	Data Hold Time. $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ High to EMDATA Invalid.	0		ns
97	Data Driving End Point. $\overline{\text{EMBSH0-3}}$, $\overline{\text{EMBSL0-3}}$, $\overline{\text{EACEN}}$ High to EMDATA Inactive _b		9	ns

- a. A RAM with hold time from address change to data change is required.
- b. Failure to meet this value may result in contention on EMDATA if a write access follows.

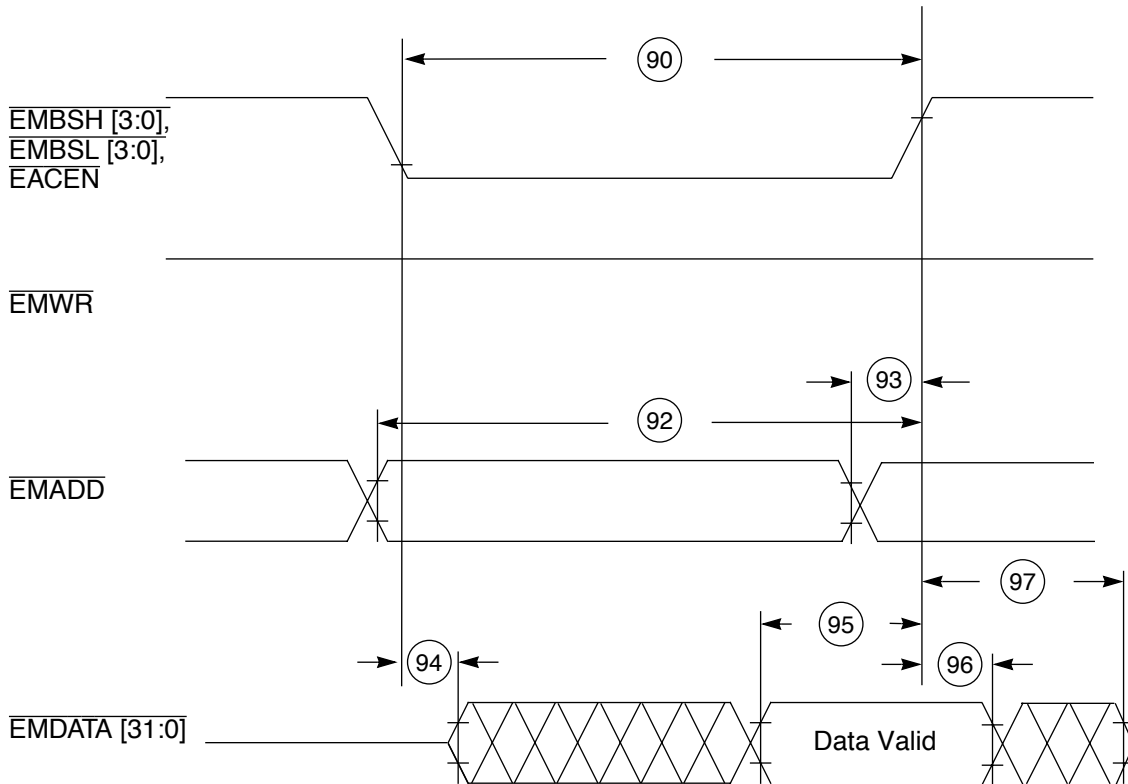


Figure 23. External Memory Read Access Timing

9.1.8 DC Electrical Characteristics
Table 3. Preliminary Electrical Characteristics

ABSOLUTE MAXIMUM RATINGS			
Symbol	Parameter	Value/Value Range	Unit
V_{DD}	DC Supply Voltage	-0.5 to 3.8	V
V_{in}^4	DC Input Voltage (5V Tolerant)	-0.5 to 5.8	V
$V_{out}^{4,5}$	DC Output Voltage	-0.5 to $V_{DD} + 0.5$	V
I	DC Current Drain per Pin, Any Single Input or Output	± 50	mA
I	DC Current Drain VDD and VSS Pins	± 100	mA
T_{stg}	Storage Temperature	-65 to +150	$^{\circ}C$
T_L	Lead Temperature (10 second soldering)	300	$^{\circ}C$

Note: Maximum ratings are those values beyond which damage to the device may occur.

RECOMMENDED OPERATING CONDITIONS (to guarantee functionality)				
Symbol	Parameter	Min	Max	Unit
V_{DD}	DC Supply Voltage, $V_{DD} = 3.3V$ (Nominal)	3.0	3.6	V
V_{in}^4	Input Voltage (5V Tolerant)	0	5.5	V
T_A	Commercial Operating Temperature	0	70	$^{\circ}C$

Notes:

1. All parameters are characterized for DC conditions after thermal equilibrium has been established.
2. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}).
3. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.
4. All input, bidirectional, and \overline{MDTACK} are 5 V Tolerant. For proper operation it is recommended that V_{in} and V_{out} be constrained to $0 \leq (V_{in}, V_{out}) \leq 5.5 V$.
5. SRXDATAx, SRXSOC, SRXPRTY, TDO 3-State outputs must be constrained to $0 \leq V_{out} \leq V_{DD}$ in Hi-Z State.

Table 4. Preliminary DC Electrical Characteristics ($T_a = 0^\circ\text{C}$ to 70°C) $V_{DD}=3.3V\pm 0.3V$

	Parameter	Condition	Min.	Max.	Unit
V_{IH}	TTL Inputs (5V Tolerant)		2.2	5.5	V
V_{IL}	TTL Inputs (5V Tolerant)		-0.3	0.8	V
I_{in}	Input Leakage Current, No Pull Resistor	$V_{in} = V_{DD}$ or V_{SS}	-5	5	μA
	with Pullup Resistor *		-50	-5	
	with Pulldown Resistor *		5	50	
I_{OH}^\dagger	Output High Current, LVTTTL Output Type Outputs: <u>EACEN</u> , <u>EMWR</u> , <u>EMADDx</u> , <u>EMBSHx</u> , <u>EMBSLx</u>	$V_{DD} = \text{Min}$, $V_{OH} \text{ Min} = 0.8 V_{DD}$	-24	-	mA
	Output High Current, LVTTTL Output Type Outputs: All other outputs		-4	-	
I_{OL}	Output Low Current, LVTTTL Output Type Outputs: <u>EACEN</u> , <u>EMWR</u> , <u>EMADDx</u> , <u>EMBSHx</u> , <u>EMBSLx</u>	$V_{DD} = \text{Min}$, $V_{OL} \text{ Max} = 0.4 \text{ Volts}$	24	-	mA
	Output Low Current, LVTTTL Output Type Outputs: All other outputs		4	-	
I_{oz}	Output Leakage Current, 3-State Output	Output = Hi Impedance $V_{out} = V_{DD}$ or V_{SS}	-10	10	μA
I_{DDQ}	Max Quiescent Supply Current	$I_{out} = 0\text{mA}$ $V_{in} = V_{DD}$ or V_{SS}	TBD		mA
I_{DD}	Max Dynamic Supply Current	nominal load capacita- tance, ACLK = 25.6Mhz, MCLK = 33Mhz	TBD		mA
C_i	Input Capacitance (TTL)			8	pF

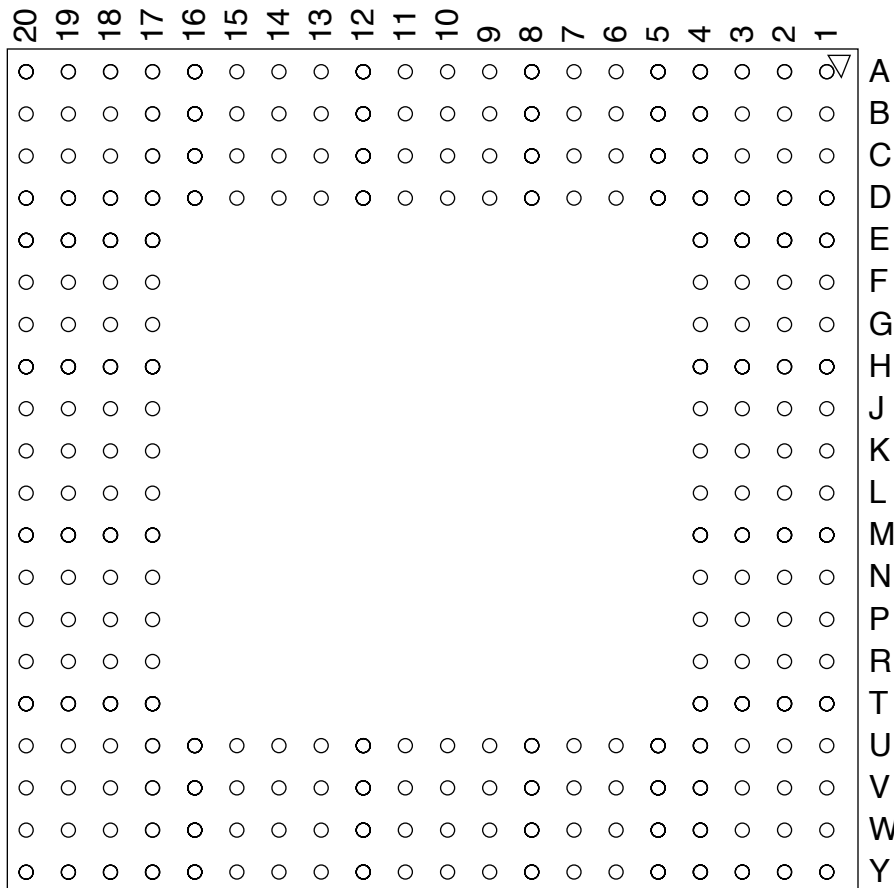
* Inputs may be modified to include pull resistors at any time.

10. PACKAGE INFORMATION
10.1 Pin Assignment
Table 5. Functional Pin Assignment

Package Pin	Signal Name	Package Pin	Signal Name	Package Pin	Signal Name	Package Pin	Signal Name	Package Pin	Signal Name	Package Pin	Signal Name
C3	TESTOUT	A8	MSEL	A14	SRXDATA:0	E17	RXDATA:3	J19	EMDATA:18	R19	EMADD:23
A2	ACLK	D9	MCIREQ	B14	SRXCLK	C20	RXDATA:2	J20	EMDATA:17	P17	EMADD:22
B2	TESTSEL	C9	MCOREQ	C14	SRXCLAV	D19	RXDATA:1	K17	EMDATA:16	R18	EMADD:21
D5	MADD:17	B9	MDTACK	A15	SRXSOC	E18	RXDATA:0	K18	EMDATA:15	T20	EMADD:20
A3	MADD:16	A9	MINT	B15	SRXPRTY	D20	EMDATA:31	K19	EMDATA:14	T19	EMADD:19
B4	MADD:15	D10	EMMREQ	D14	N/C	E19	EMDATA:30	K20	EMDATA:13	U20	EMADD:18
C5	MADD:14	C10	MCLK	C15	N/C	F18	EMDATA:29	L20	EMDATA:12	V20	EMADD:17
A4	MADD:13	B10	MWR	A16	RXSOC	G17	EMDATA:28	L18	EMDATA:11	T17	EMADD:16
B5	MADD:12	A10	MWSH	B16	RXENB	E20	EMDATA:27	L19	EMDATA:10	U18	EMADD:15
C6	MADD:11	A11	MWSL	C16	RXEMPTY	F19	EMDATA:26	M20	EMDATA:9	U19	EMADD:14
D7	MADD:10	C11	MDS	A17	RXPHYID:3	G18	EMDATA:25	M19	EMDATA:8	V18	EMADD:13
A5	MADD:9	B11	SRXENB	A18	RXPHYID:2	F20	EMDATA:24	M18	EMDATA:7	Y19	EMADD:12
B6	MADD:8	A12	SRXDATA:7	D16	RXPHYID:1	G19	EMDATA:23	M17	EMDATA:6	W18	EMADD:11
C7	MADD:7	B12	SRXDATA:6	C17	RXPHYID:0	G20	EMDATA:22	N20	EMDATA:5	V17	EMADD:10
A6	MADD:6	C12	SRXDATA:5	B17	RXPRTY	H18	EMDATA:21	N19	EMDATA:4	U16	EMADD:9
B7	MADD:5	D12	SRXDATA:4	C18	RXDATA:7	H19	EMDATA:20	N18	EMDATA:3	Y18	EMADD:8
A7	MADD:4	A13	SRXDATA:3	B20	RXDATA:6	H20	EMDATA:19	P20	EMDATA:2	W17	EMADD:7
C8	MADD:3	B13	SRXDATA:2	C19	RXDATA:5	J17	EACEN	P19	EMDATA:1	Y17	EMADD:6
B8	MADD:2	C13	SRXDATA:1	D18	RXDATA:4	J18	EMWR	R20	EMDATA:0	W16	EMADD:5
V15	EMADD:4	W10	TDO	U5	TXPRTY	P1	MDATA:25	H2	MDATA:5		
U14	EMADD:3	Y9	TDI	V4	TXSOC	N3	MDATA:24	H3	MDATA:4		
Y16	EMADD:2	W9	ENID	W4	TXDATA:7	N2	MDATA:23	G1	MDATA:3		
W15	N/C	V9	STXCLK	V3	TXDATA:6	N1	MDATA:22	G2	MDATA:2		
Y15	EMBSH:0	U9	STXCLAV	W1	TXDATA:5	M4	MDATA:21	G3	MDATA:1		
W14	EMBSH:1	Y8	STXSOC	V2	TXDATA:4	M3	MDATA:20	F1	MDATA:0		
Y14	EMBSH:2	W8	STXPRTY	U3	TXDATA:3	M2	MDATA:19	F2	MADD:25		
V13	EMBSH:3	V8	STXDATA:7	T4	TXDATA:2	M1	MDATA:18	G4	MADD:24		
W13	N/C	Y7	STXDATA:6	V1	TXDATA:1	L4	MDATA:17	F3	MADD:23		
Y13	EMBSL:0	W7	STXDATA:5	U2	TXDATA:0	L3	MDATA:16	E1	MADD:22		
U12	EMBSL:1	V7	STXDATA:4	T3	TXPHYID:3	L2	MDATA:15	E2	MADD:21		
V12	EMBSL:2	Y6	STXDATA:3	U1	TXPHYID:2	L1	MDATA:14	E3	MADD:20		
W12	EMBSL:3	W6	STXDATA:2	T2	TXPHYID:1	K1	MDATA:13	D1	MADD:19		
Y12	N/C	U7	STXDATA:1	R3	TXPHYID:0	K3	MDATA:12	C1	MADD:18		
U11	AMODE:1	V6	STXDATA:0	P4	MDATA:31	K2	MDATA:11	D2	VCOCTL		
V11	AMODE:0	Y5	STXENB	T1	MDATA:30	J1	MDATA:10				
W11	ARST	W5	TXENB	R2	MDATA:29	J2	MDATA:9				
Y11	TCK	V5	TXFULL	P3	MDATA:28	J3	MDATA:8				
Y10	TRST	Y4	TXCLR	R1	MDATA:27	J4	MDATA:7				
V10	TMS	Y3	TXPHYIDV	P2	MDATA:26	H1	MDATA:6				

10. PACKAGE INFORMATION

256 PBGA Pin Diagram/Power Pin Assignment (Bottom View)



VDD - D6, D11, D15, F4, F17, K4, L17, R4, R17, U6, U10, U15, B19, B18, C4, D3, W2, Y2, V19, W19, P18, V14

VSS - A1, D4, D8, D13, D17, H4, H17, N4, N17, U4, U8, U13, U17, A19, A20, B3, E4, Y1, W3, Y20, W20, T18, V16

AVDD - C2

AVSS - B1

NOTE: To eliminate coupling of digital switching noise into the PLL through pins AVDD and AVSS, it is recommended to connect these pins to isolated power and ground.

Table 6. Signal Pin Allocation

Block name	Number of pins
MP	67
PHY	34
SWT	26
External memory	64
JTAG	5
General/NC	13
Total Signals	209

Table 7. Power Pin Allocation

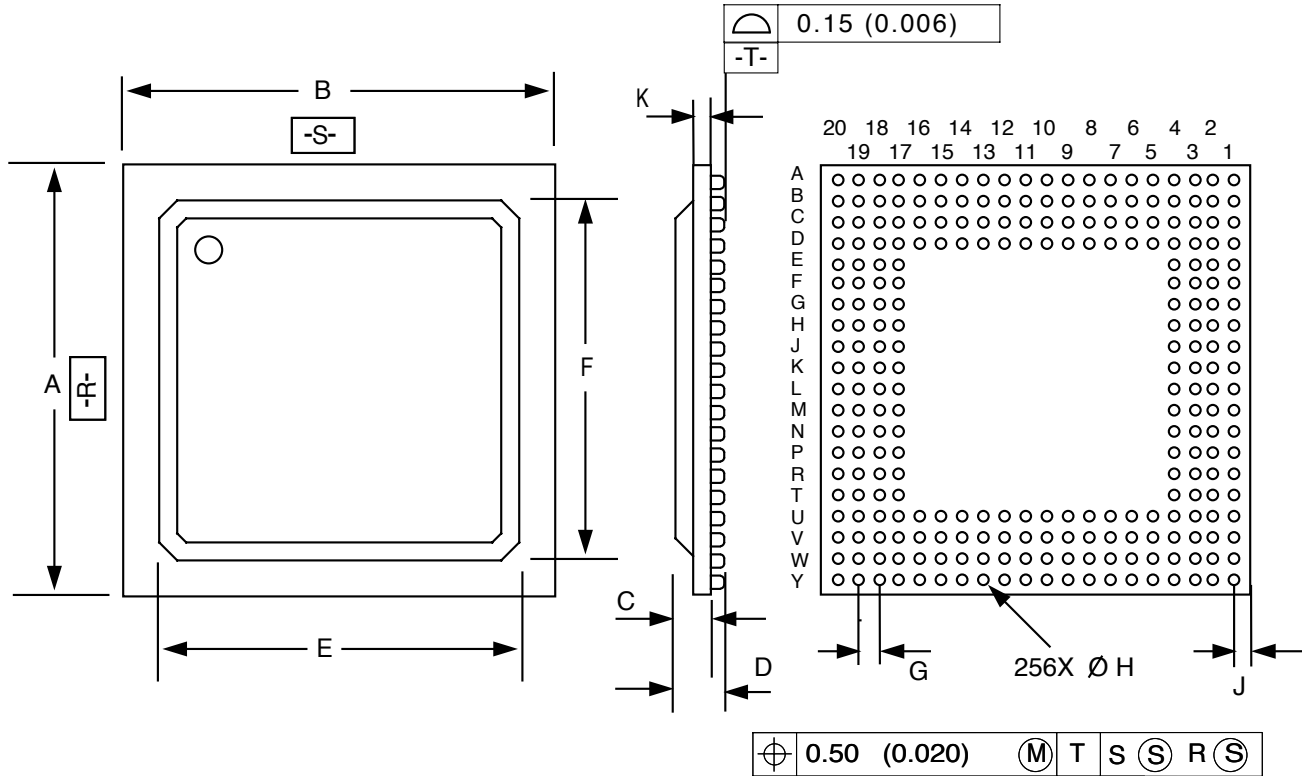
Power	Number of pins
VDD	22
VSS	23
AVDD	1
AVSS	1
Total Power	47

10. PACKAGE INFORMATION

10.2 256 PBGA Case Outline (Preliminary Drawing)

OMPAC - (used for Production) ZP Package

GTPAC - (used for Prototype and Production) ZQ Package



Dimensions for OMPAC

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	26.90	27.10	1.0590	1.0669
B	26.90	27.10	1.0590	1.0669
C	1.330	1.730	0.0523	0.0681
D	1.830	2.430	0.072	0.0956
E	23.80	24.20	0.9370	0.9527
F	23.80	24.20	0.9370	0.9527
G	1.27 BSC		.050 BSC	
H	0.690	0.810	0.0271	0.0318
J	1.335	1.535	.0526	.0604
K	0.310	0.410	0.012	0.016

Dimensions for GTPAC

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	26.90	27.10	1.0590	1.0669
B	26.90	27.10	1.0590	1.0669
C	1.526	2.134	0.060	0.084
D	2.026	2.834	0.080	0.112
E	17.780	22.860	0.700	0.900
F	17.780	22.860	0.700	0.900
G	1.27 BSC		.050 BSC	
H	0.690	0.810	0.0271	0.0318
J	1.335	1.535	.0526	.0604
K	0.510	0.610	0.020	0.024

NOTE:

256 OMPAC package thickness is subject to change to reflect substrate standardization, consult factory for status.

Notes:

Freescale Semiconductor, Inc.

**Home Page:**

www.freescale.com

email:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
(800) 521-6274
480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku
Tokyo 153-0064, Japan
0120 191014
+81 2666 8080
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate,
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor
Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
(800) 441-2447
303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

